

EMC in načrtovanje TIV

Marko Jankovec

Laboratorij za fotovoltaiiko in optoelektroniko
Fakulteta za Elektrotehniko, Univerza v Ljubljani

Elektromagnetna združljivost



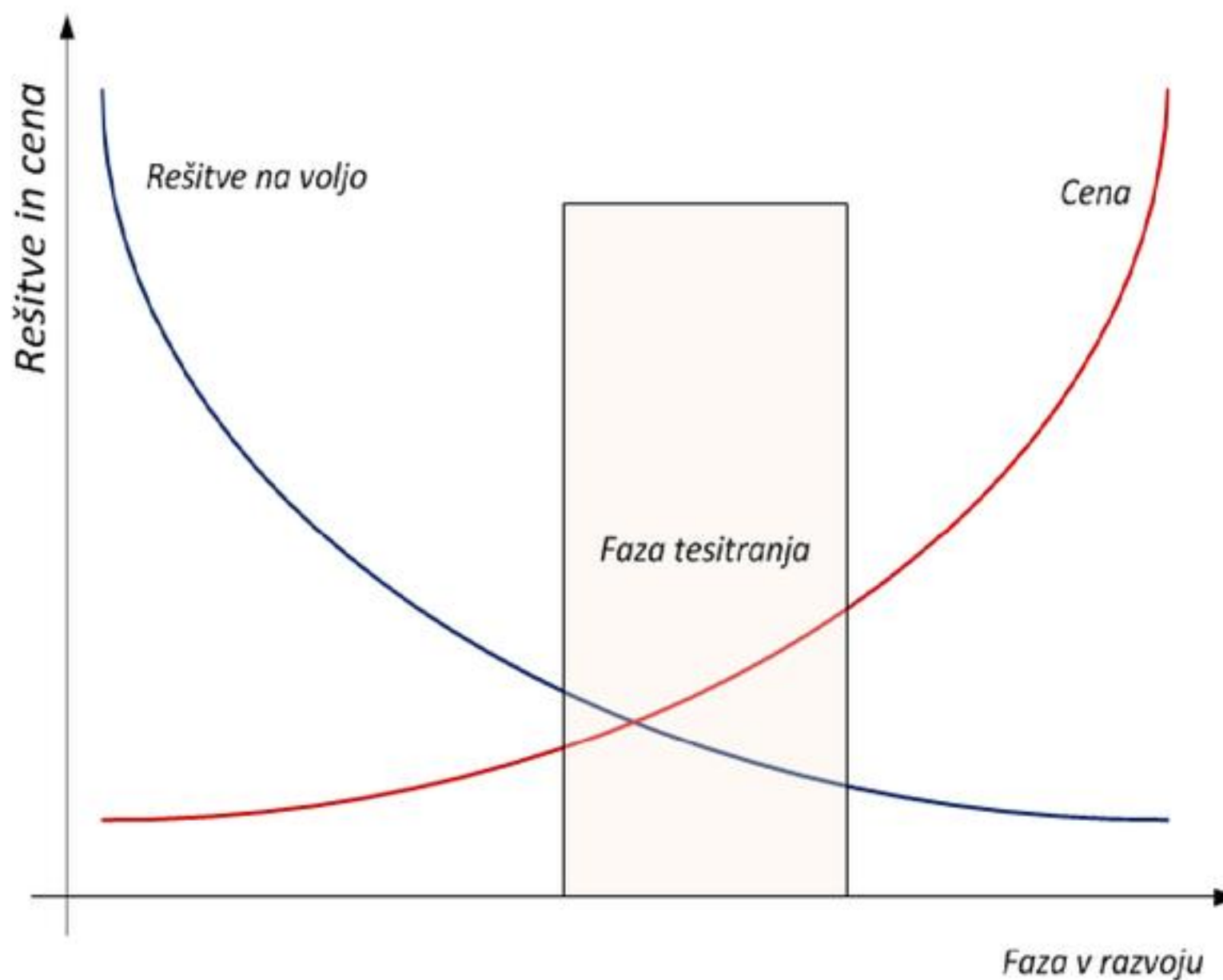
Motnja/
emisija

- Prevodna (Conducted)
- Sevalna (Radiated)

Odpornost/
imunost

- Prevodna (Conducted)
- Elektrostatska razelektritev (ESD)
- Sevalna (Radiated)

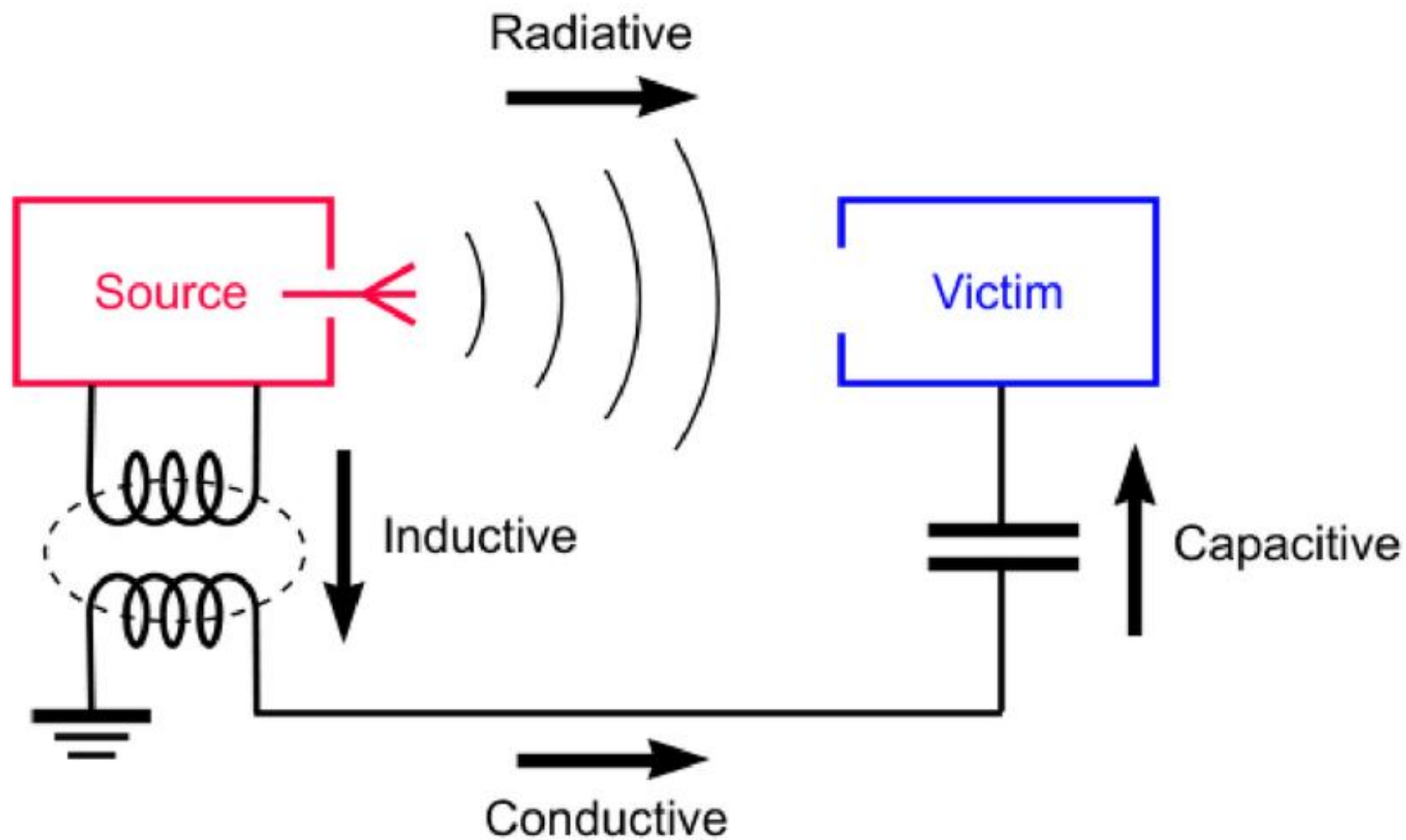
Doseganje EMC



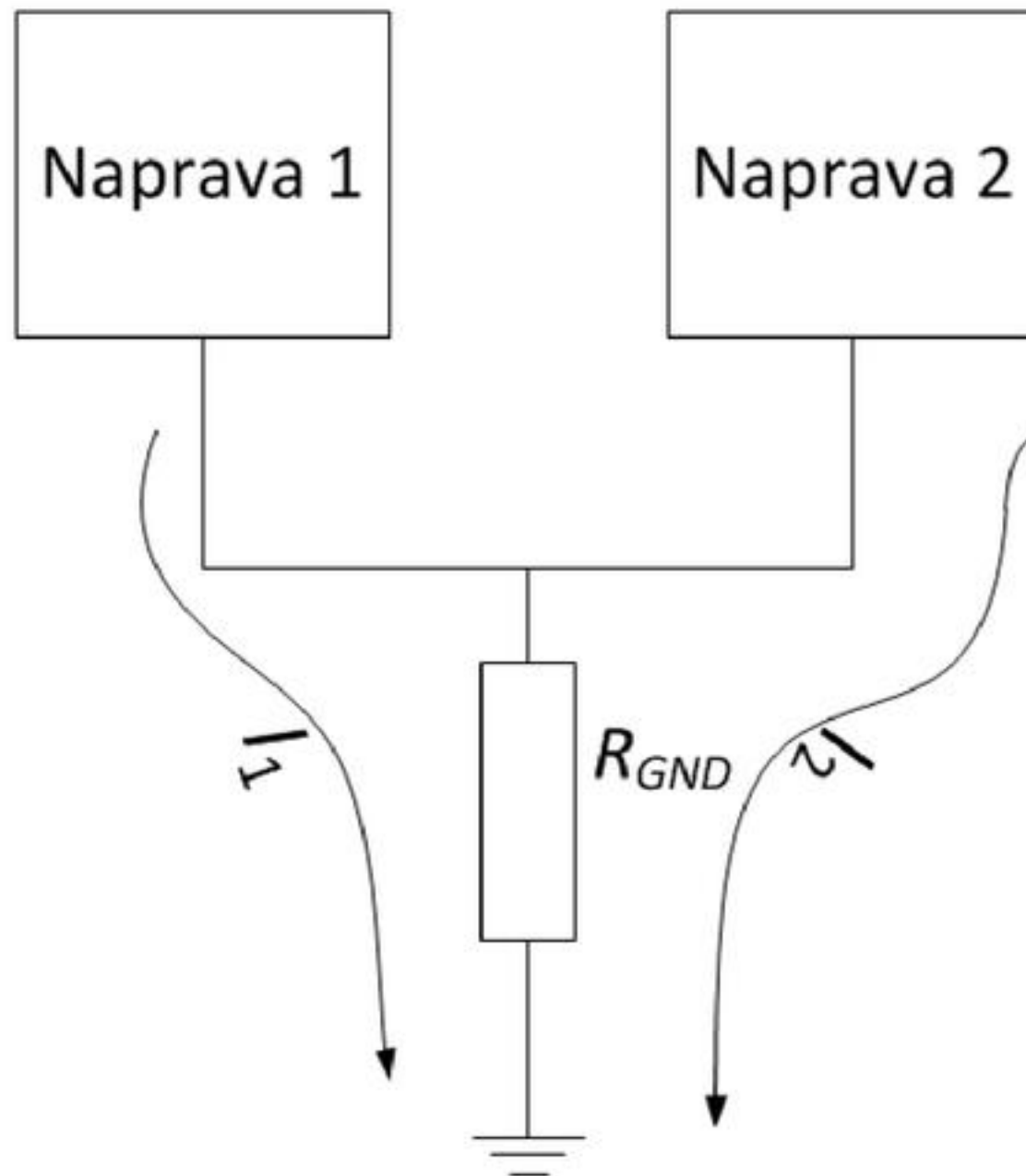
Model EMC



Povezave

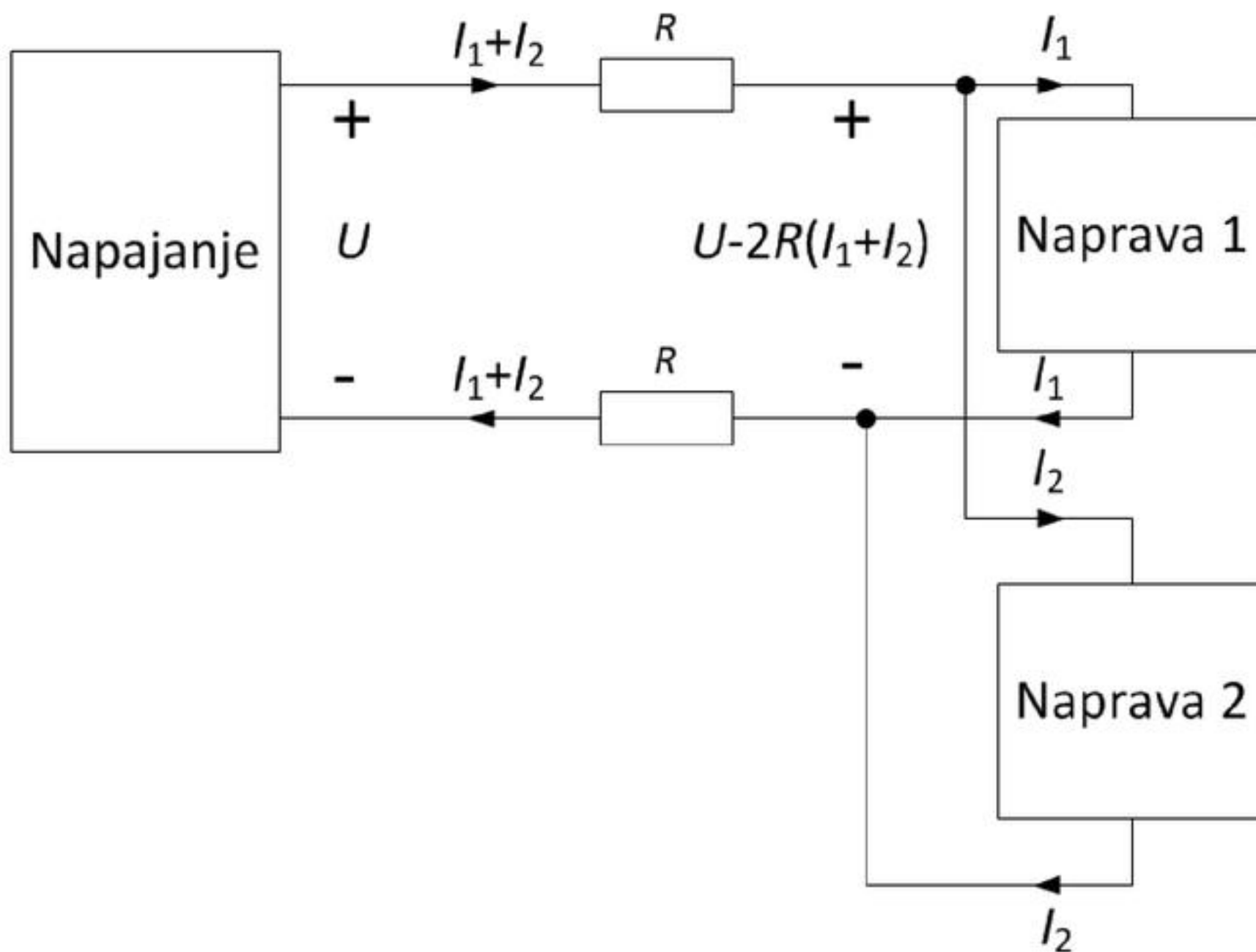


Konduktivna povezava preko skupne mase

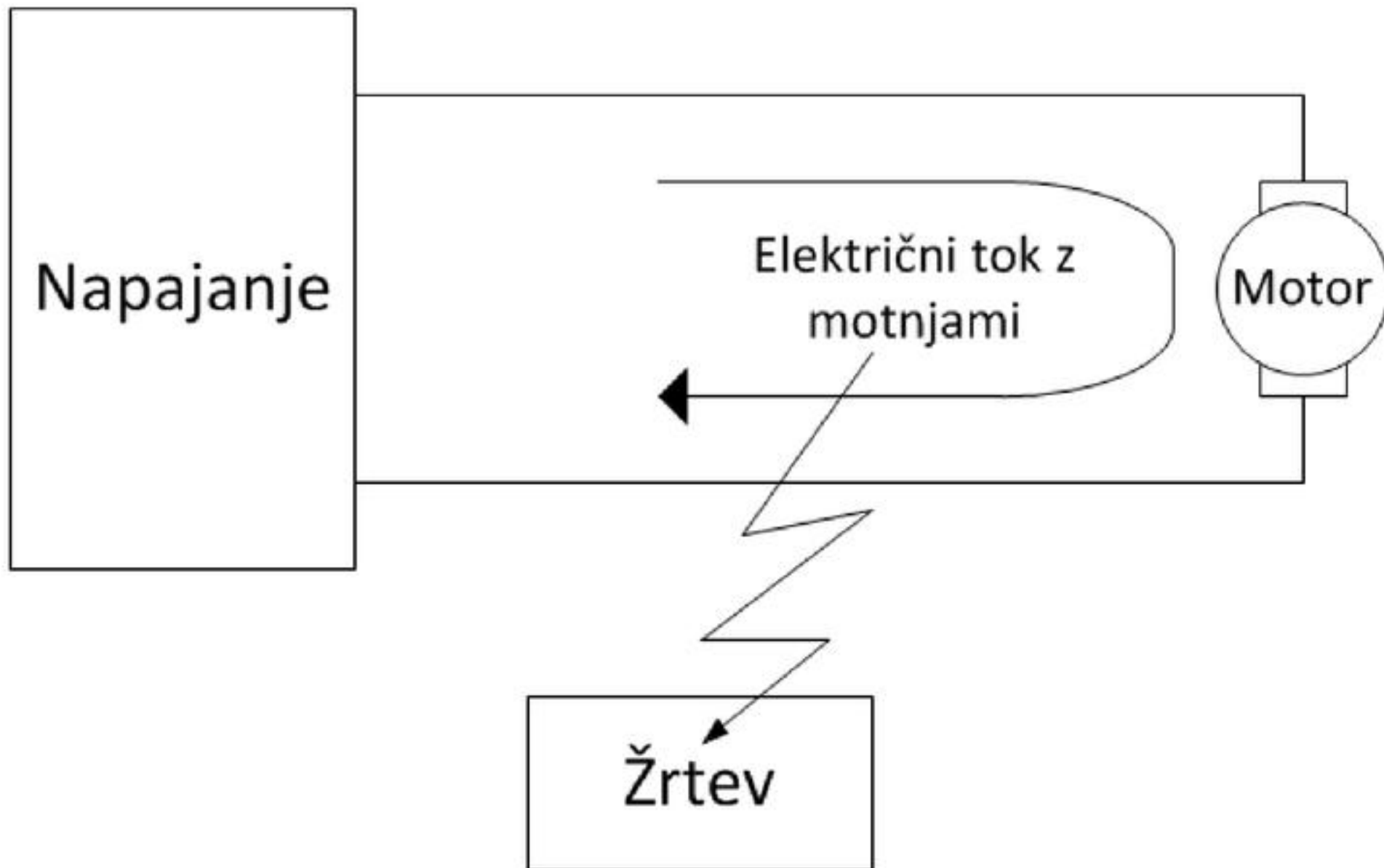


$$+ \\ U_{GND} = R_{GND} * (I_1 + I_2) \\ -$$

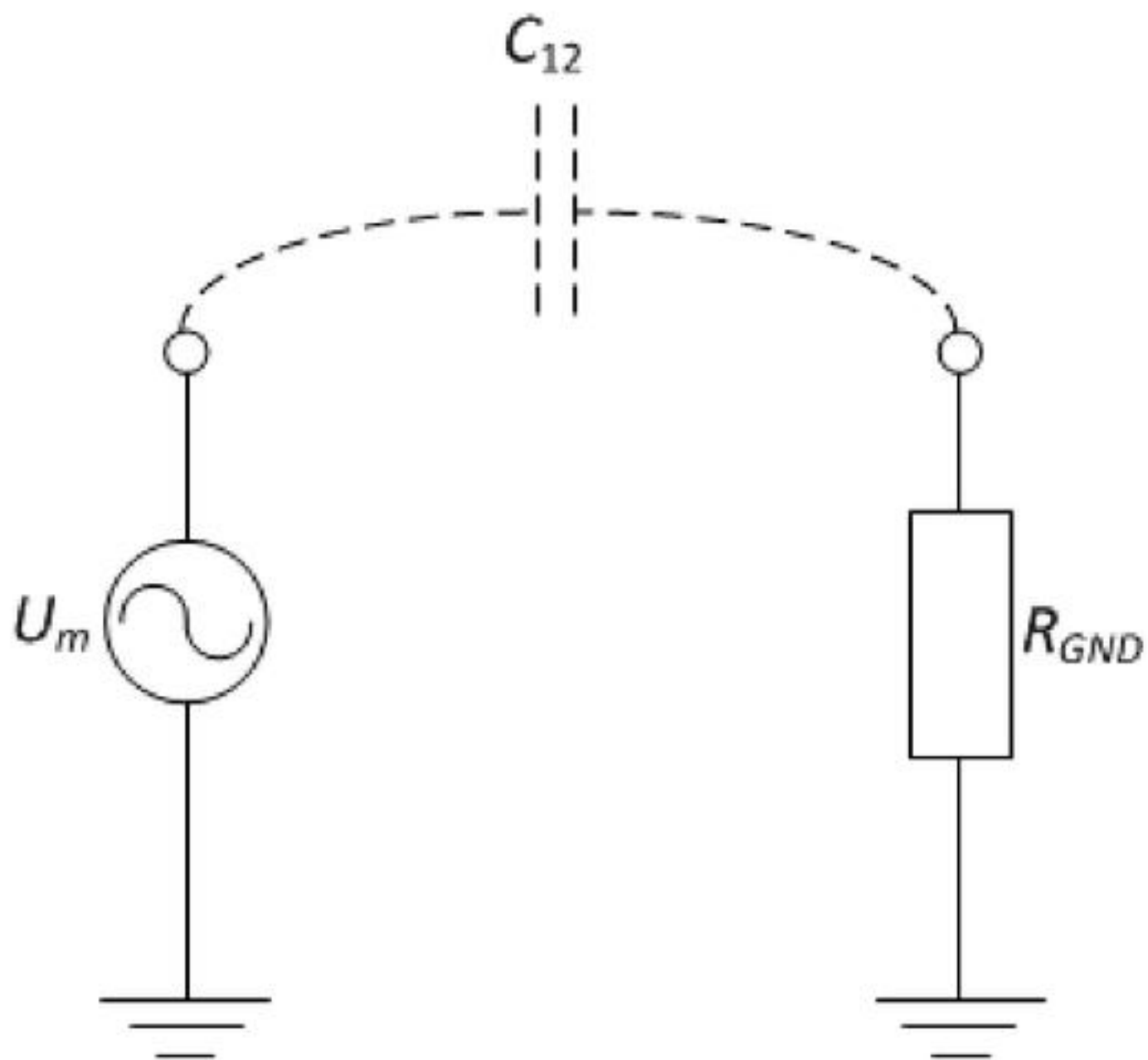
Konduktivna povezava prek napajalnih linij



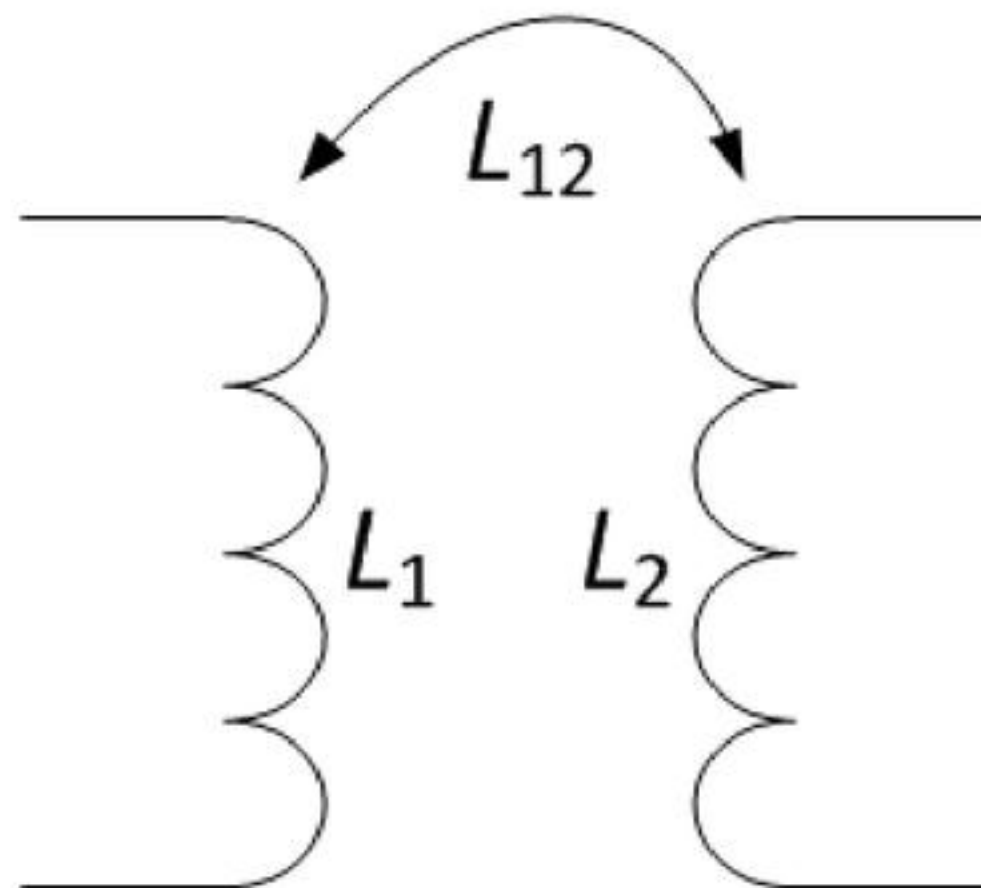
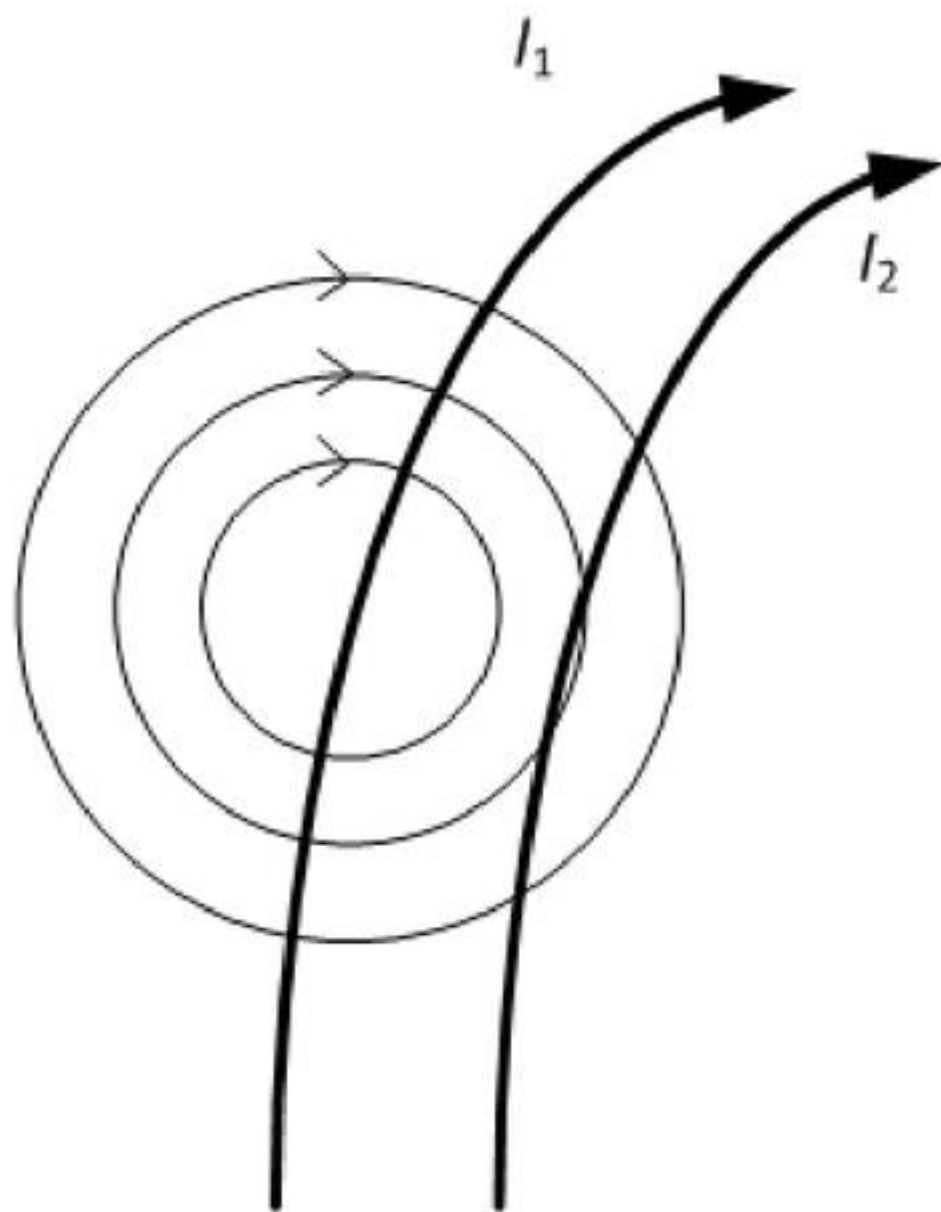
Konduktivno-radiativni prenos motenj



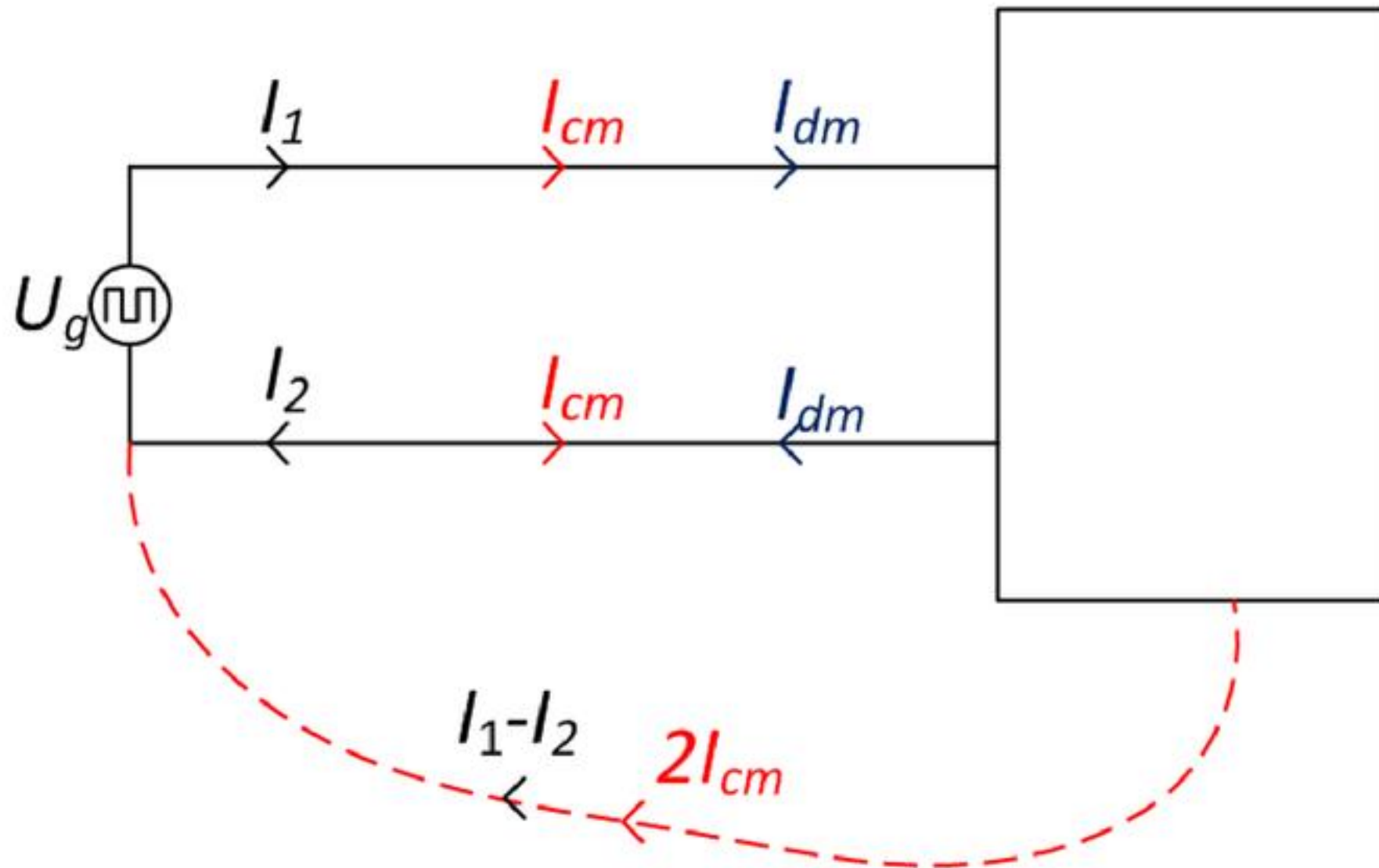
Kapacitivna povezava prek E polja



Induktivna povezava prek H polja



Diferencialni in sofazni signali



$$I_1 = I_{dm} + I_{cm}$$

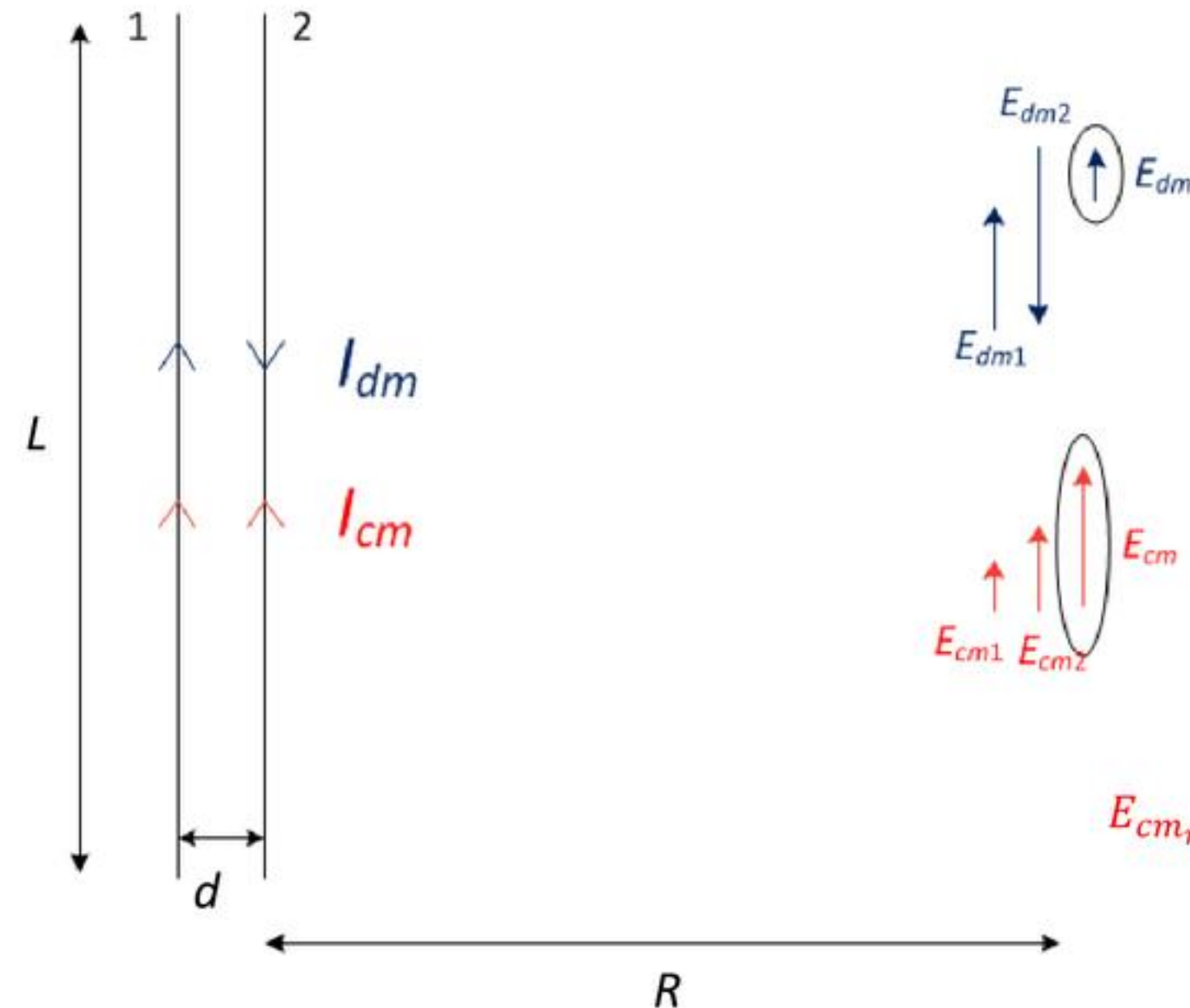
$$I_2 = I_{dm} - I_{cm}$$

$$I_{dm} = \frac{I_1 + I_2}{2}$$

$$I_{cm} = \frac{I_1 - I_2}{2}$$

Diferencialne in sofazne motnje

$$E_{dm_{maks}}(f) = 2,632 \cdot 10^{-14} \frac{I_{dm}(f) f^2 L d}{R} \text{ V/m}$$



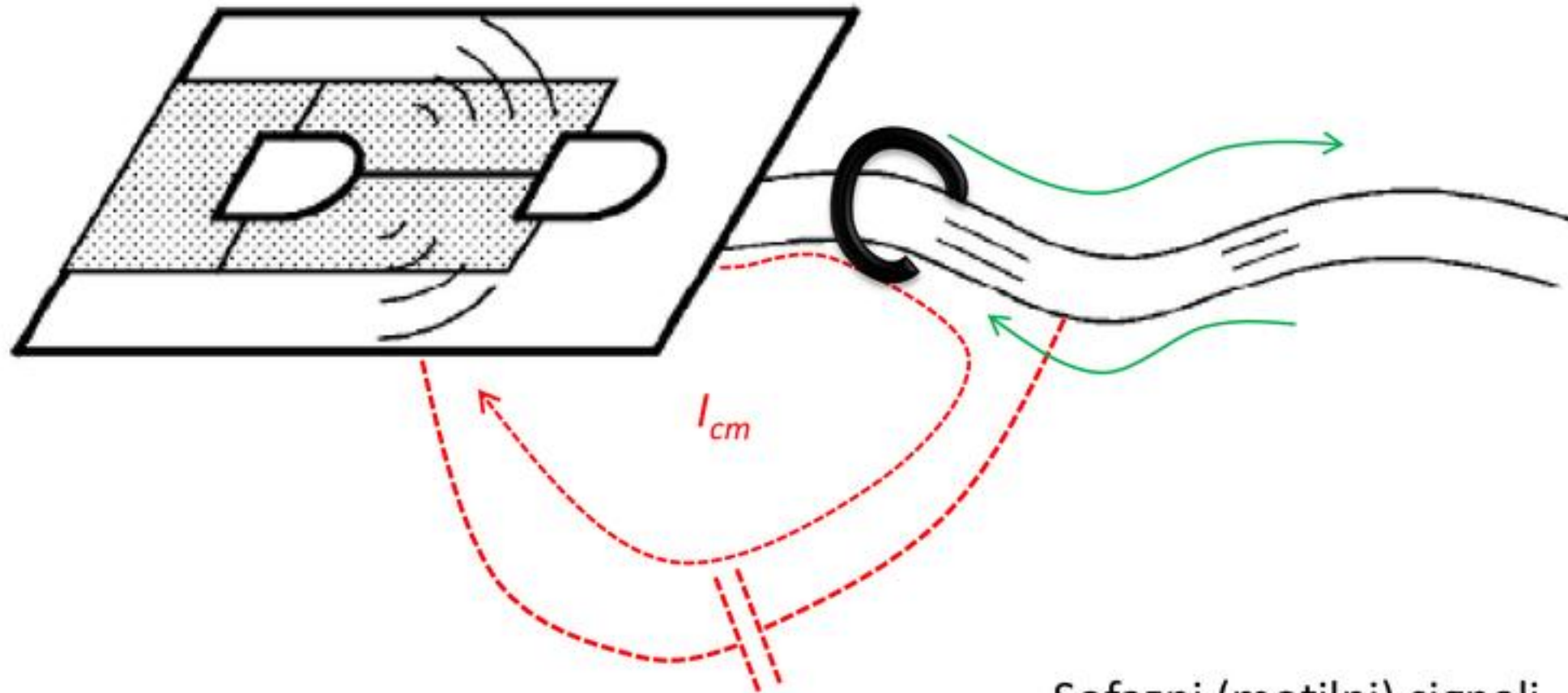
$$E_{cm_{maks}}(f) = 2,541 \cdot 10^{-6} \frac{I_{cm}(f) f L}{R} \text{ V/m}$$

Primer



- Signali na PCB
 - › Majhne tokovne zanke (A)
 - › Protifazni zančni tokovi (I)
 - › $E_{dm} = 265 \cdot 10^{-16} \frac{I_{dm} A f^2}{R}$
- $I = 1 \text{ mA}, f = 100 \text{ MHz}, A = 1 \text{ cm}^2$
- $E = 26 \frac{\mu\text{V}}{\text{m}} @ 1 \text{ m}$
- Signali na povezovalnem kablu
 - › Velike dipolne antene (dolžine L)
 - › Sofazni tokovi (I)
 - › $E_{cm} = 4 \cdot 10^{-7} \frac{I_{cm} f L}{R}$
- $I = 200 \text{ pA}, f = 100 \text{ MHz}, L = 1 \text{ m}$
- $E = 26 \frac{\mu\text{V}}{\text{m}} @ 1 \text{ m}$

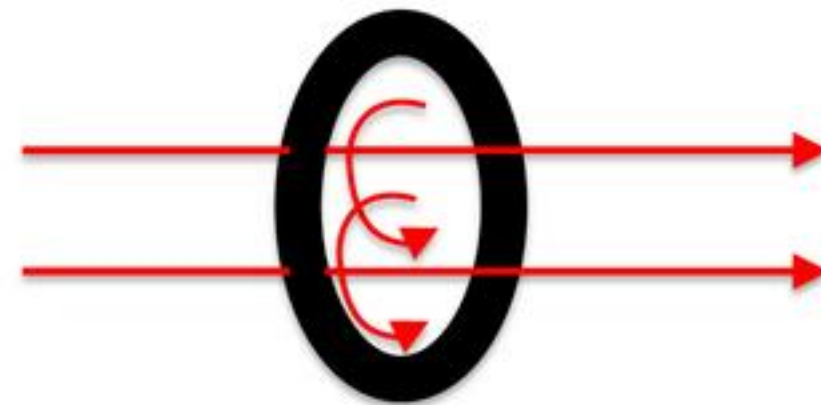
Feritni obroček



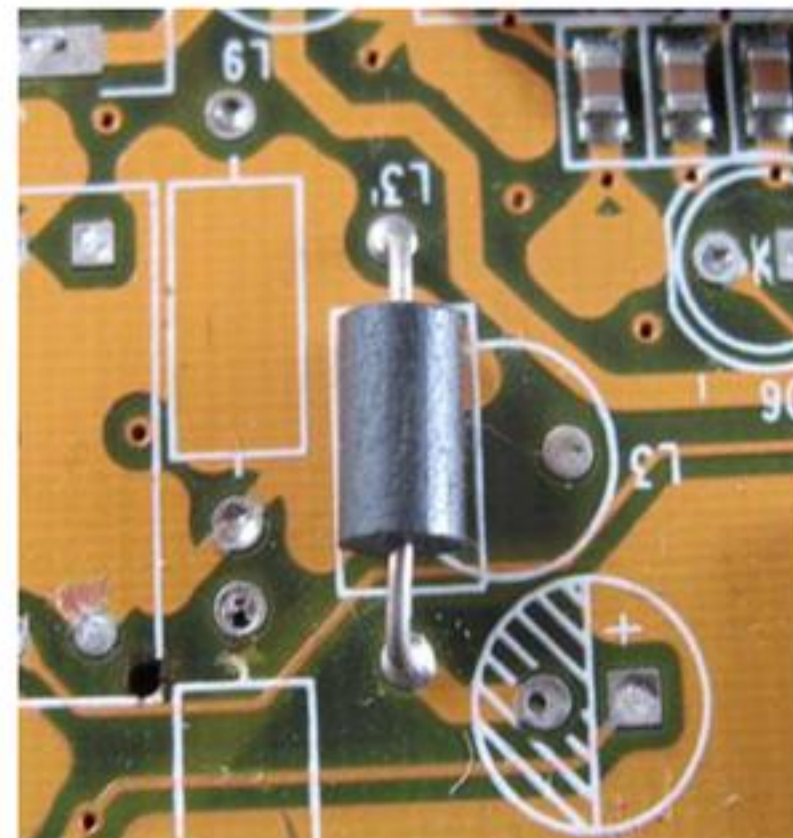
Diferencialni (koristni) signali



Sofazni (motilni) signali



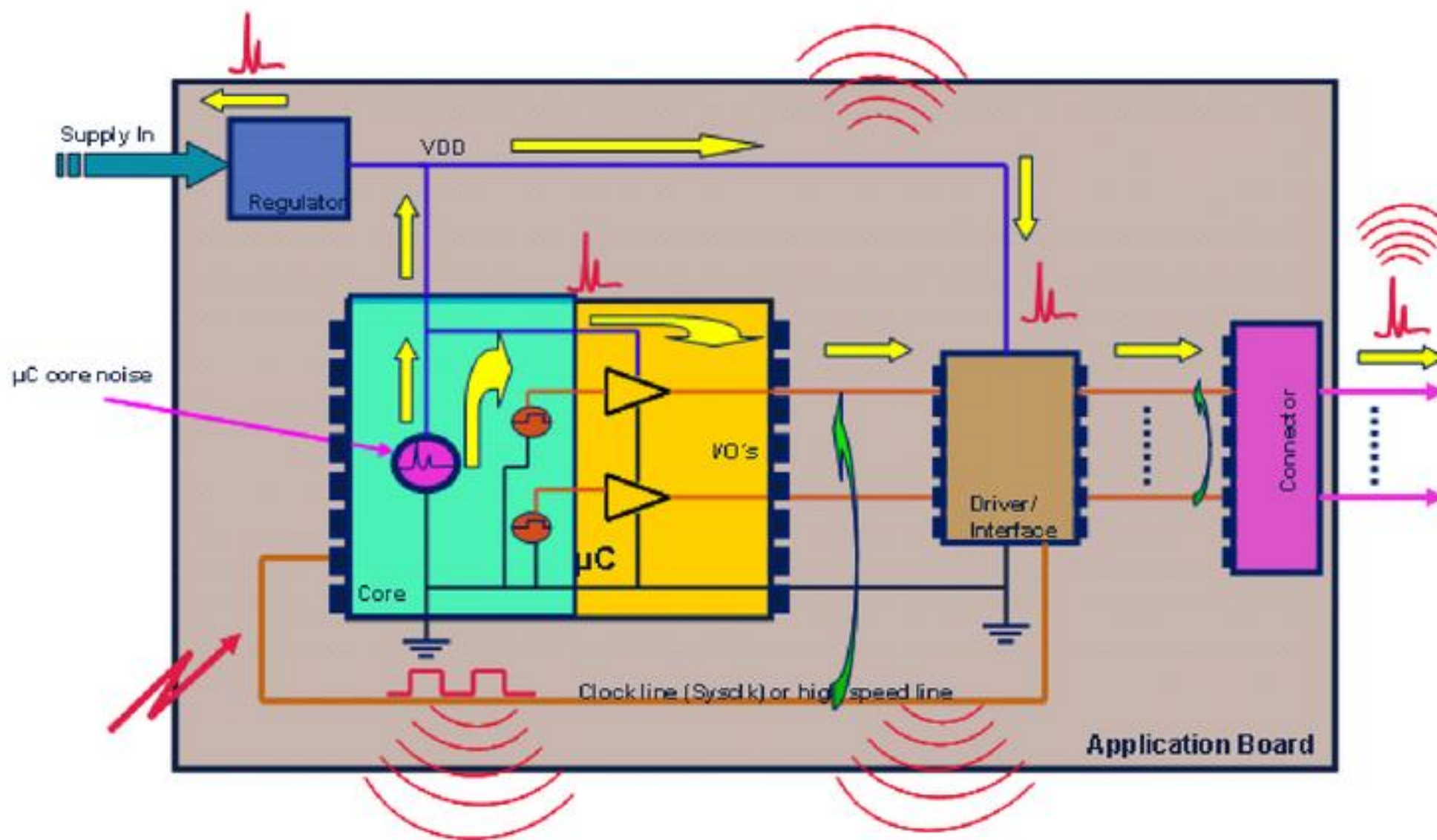
Različni feritni obročki



Kitajska tablica



Viri EMI v digitalnem elektronskem vezju



➔ Propagation path of core noise & switching noise of I/O's

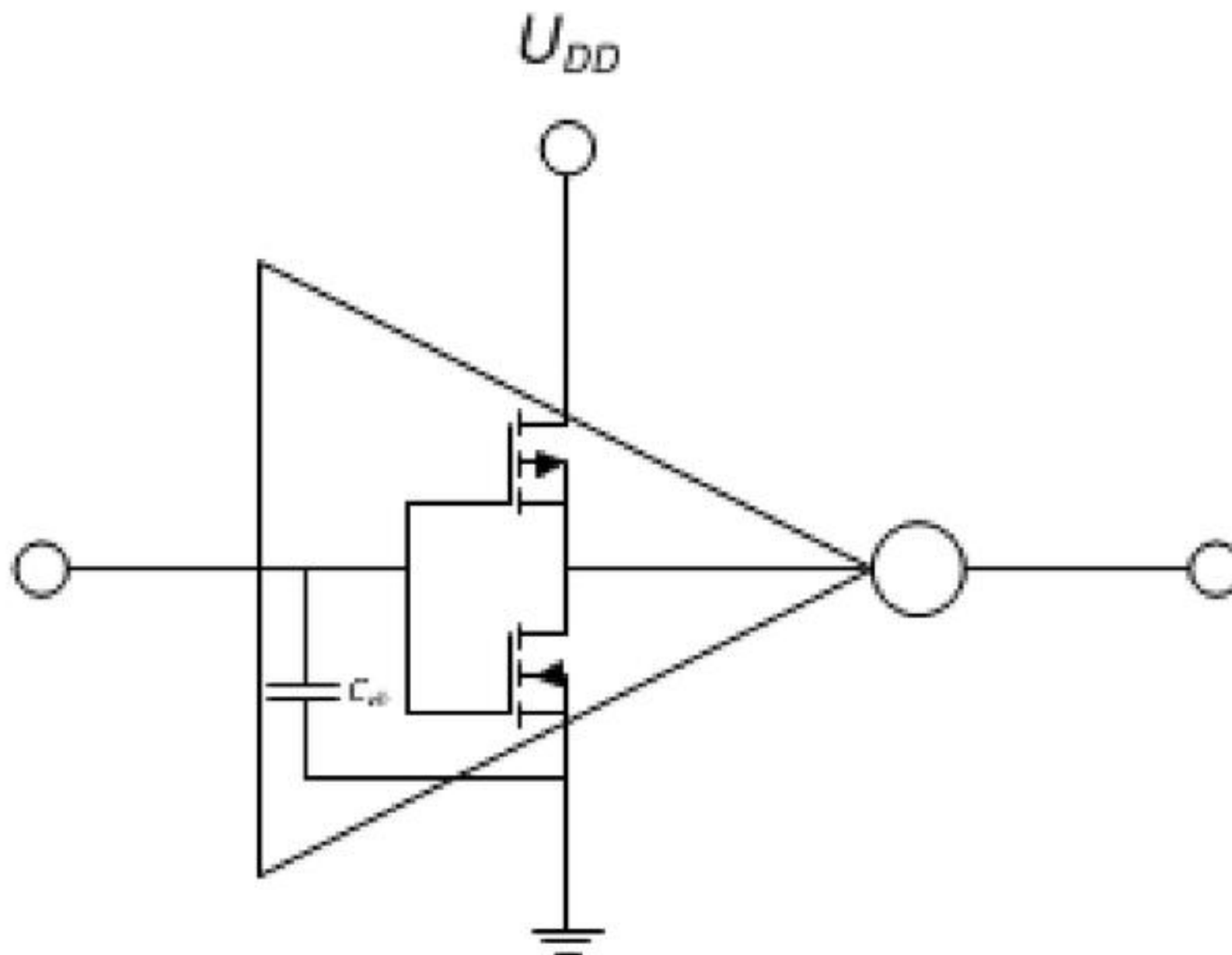
↻ Crosstalk between traces

⚡ Interference from outer sources

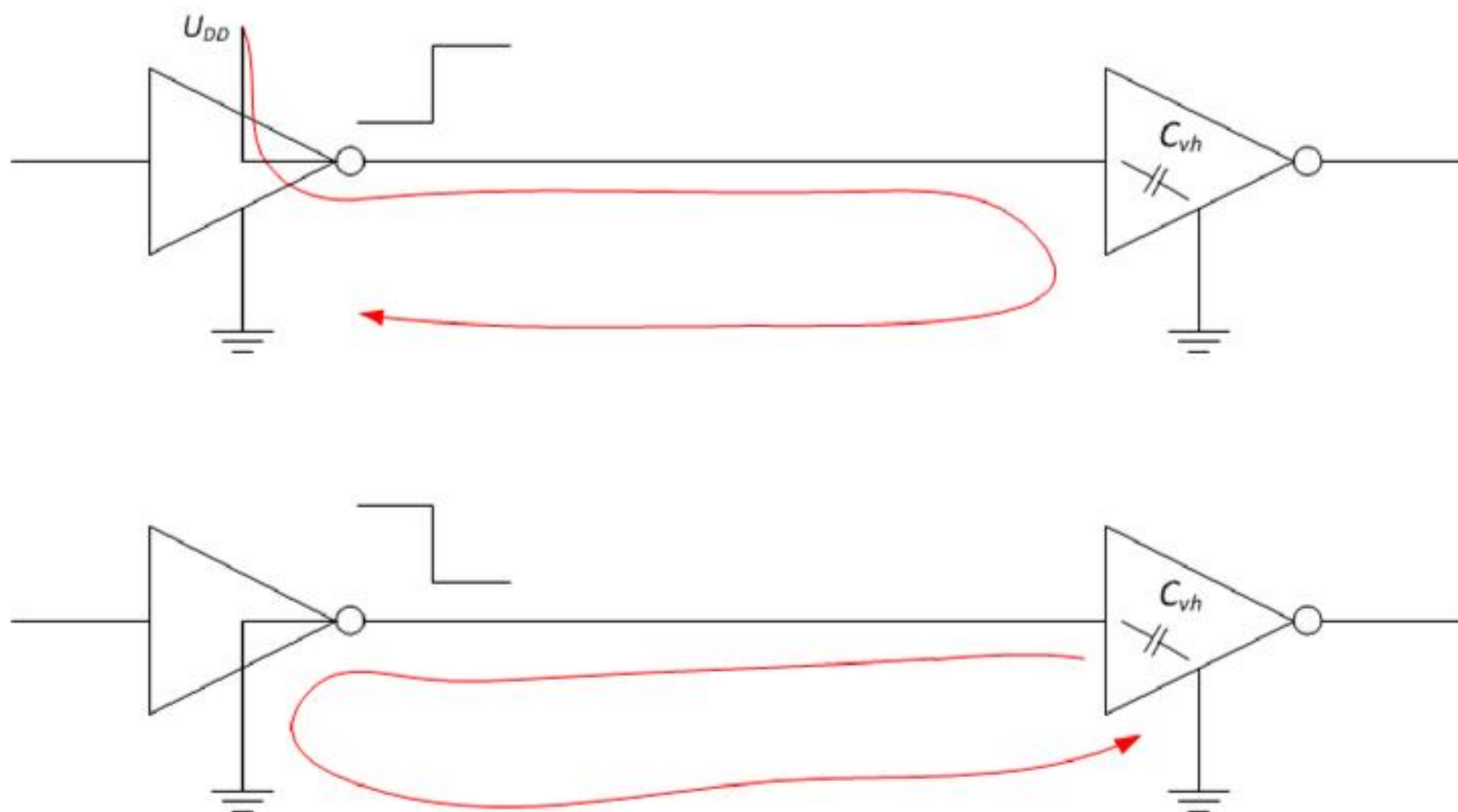
⊙ Conducted & Radiated Emission

Vir: Infineon

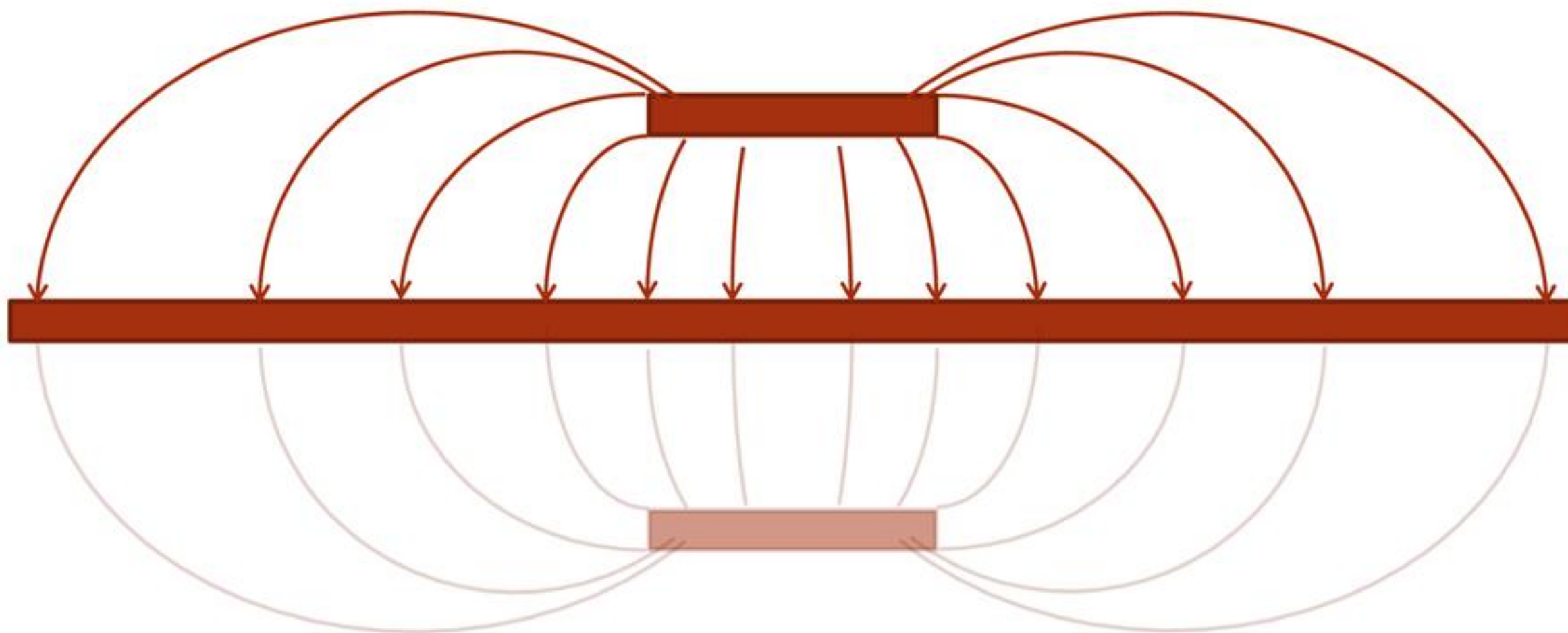
Tipično nadomestno vezje logičnih vrat



Kirchhoffov tokovni zakon velja vedno

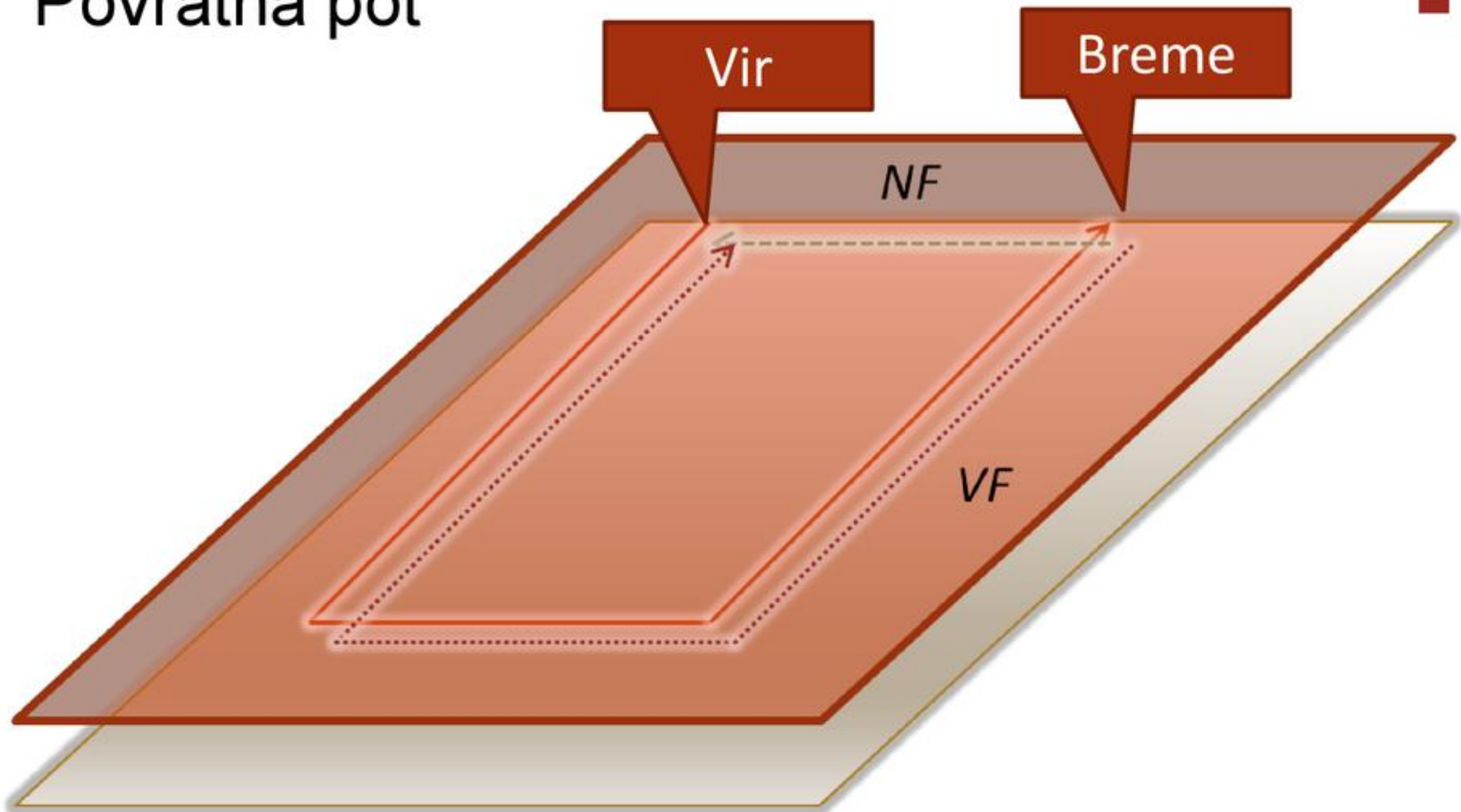


Zrcalna ravnina

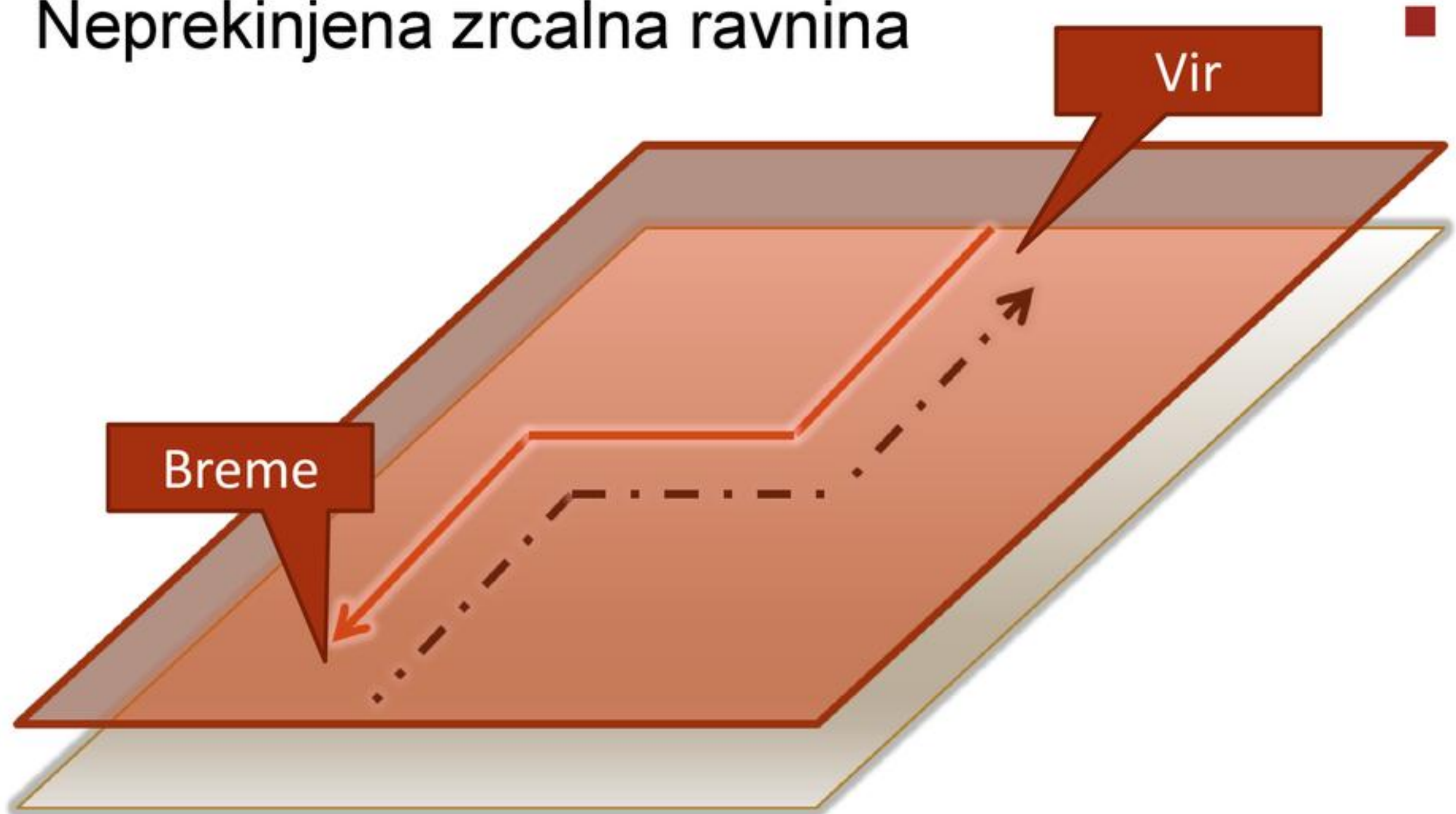


navidezna zrcalna slika

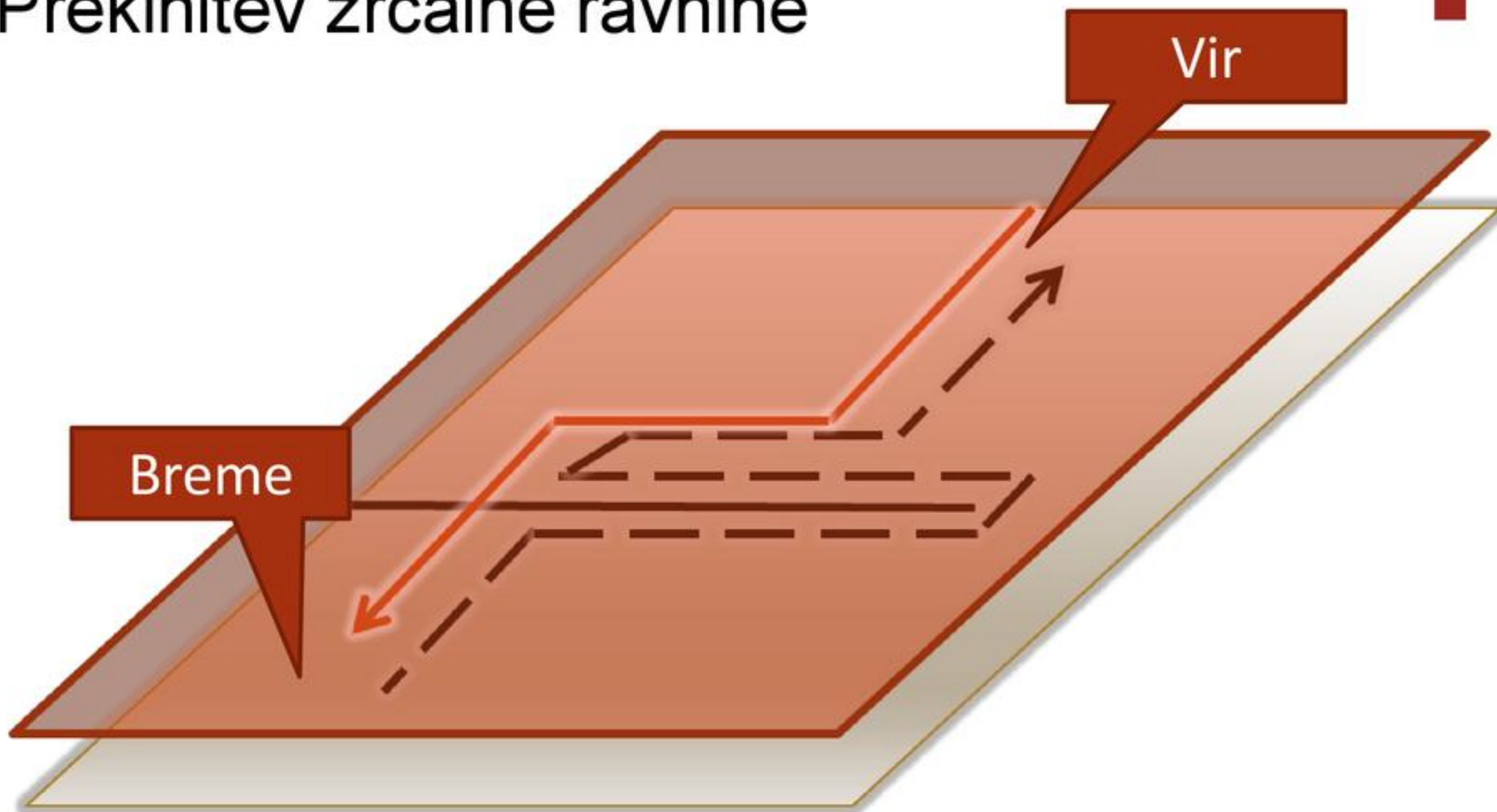
Povratna pot



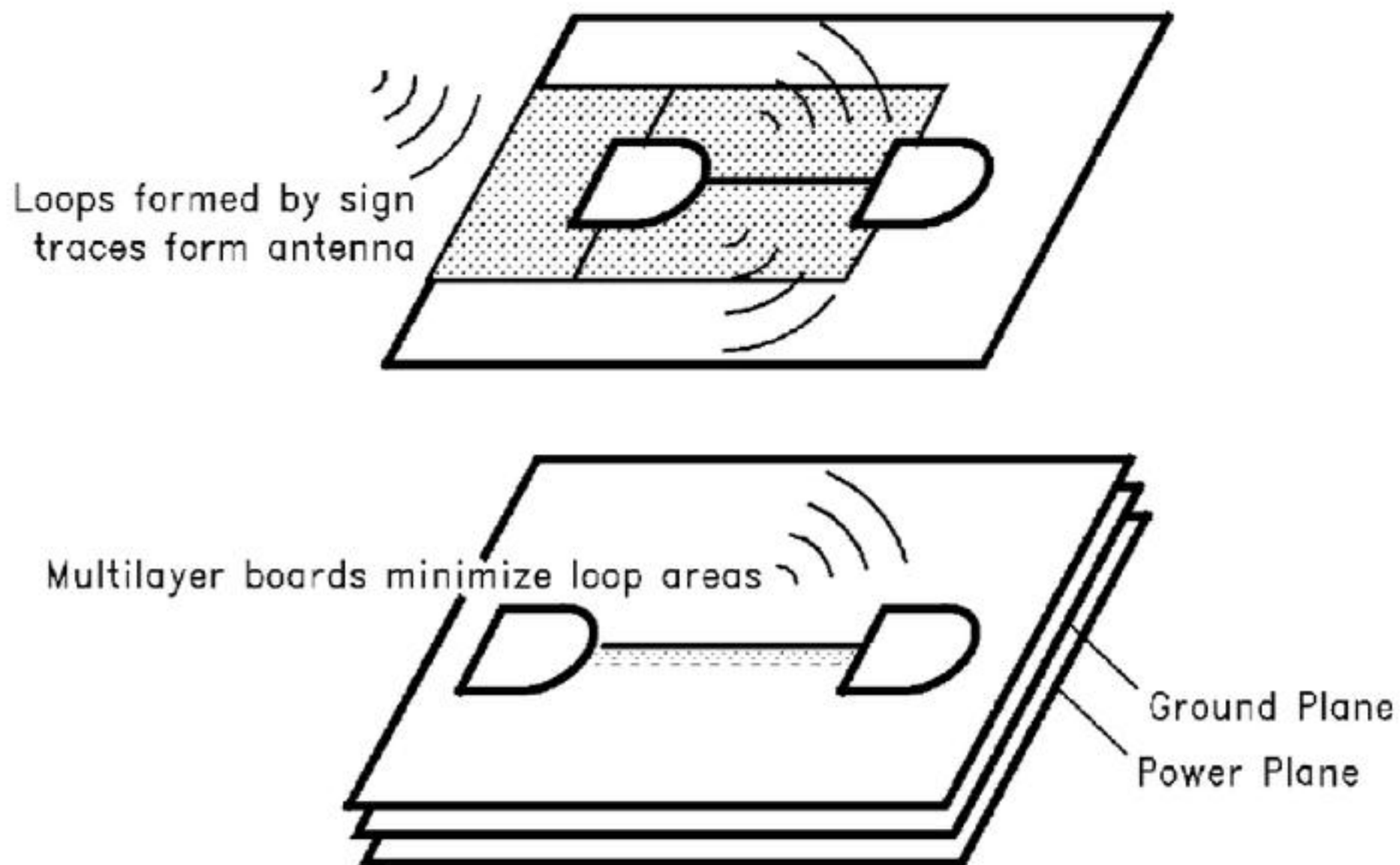
Neprekinjena zrcalna ravnina



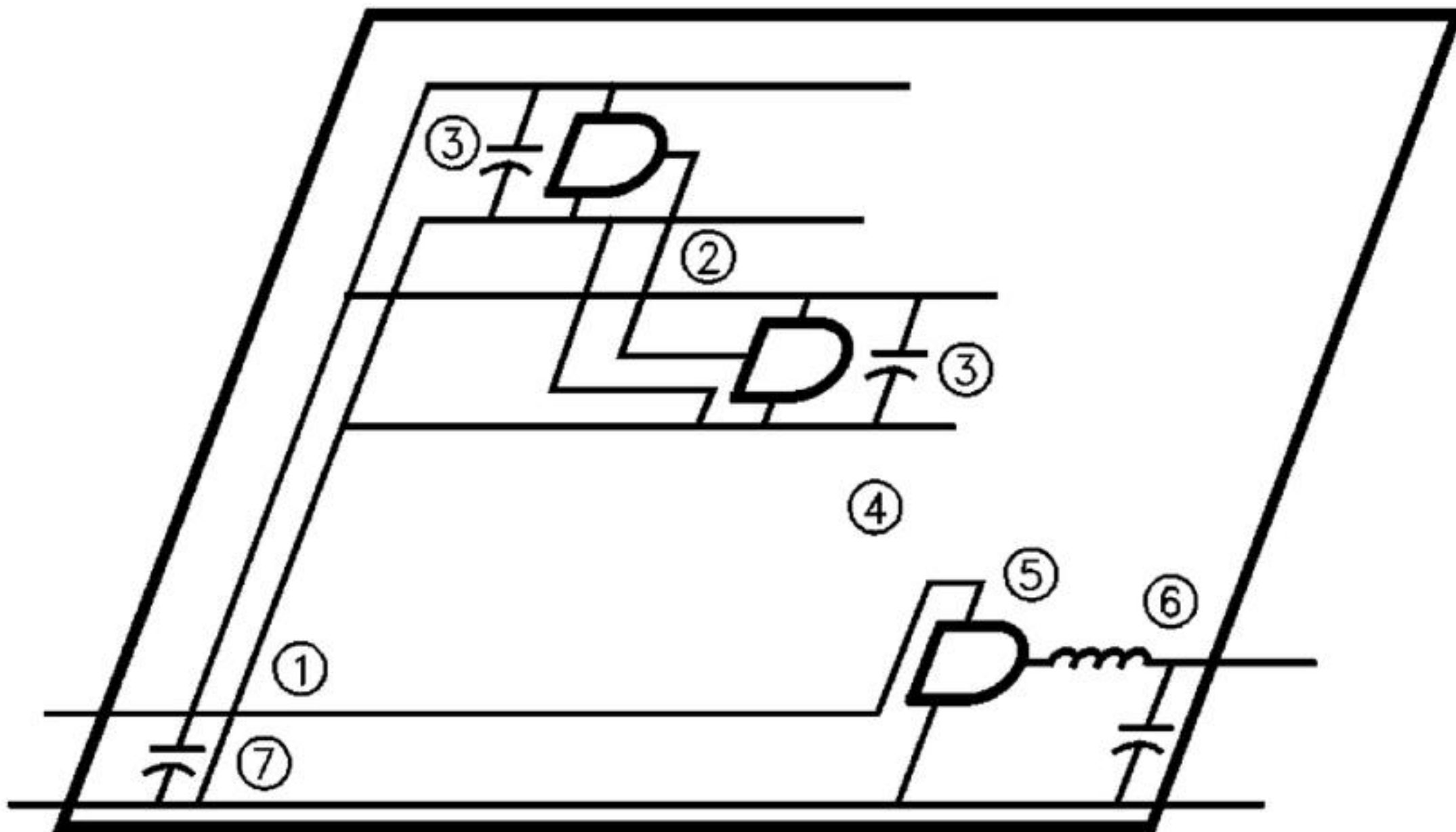
Prekinitev zrcalne ravnine



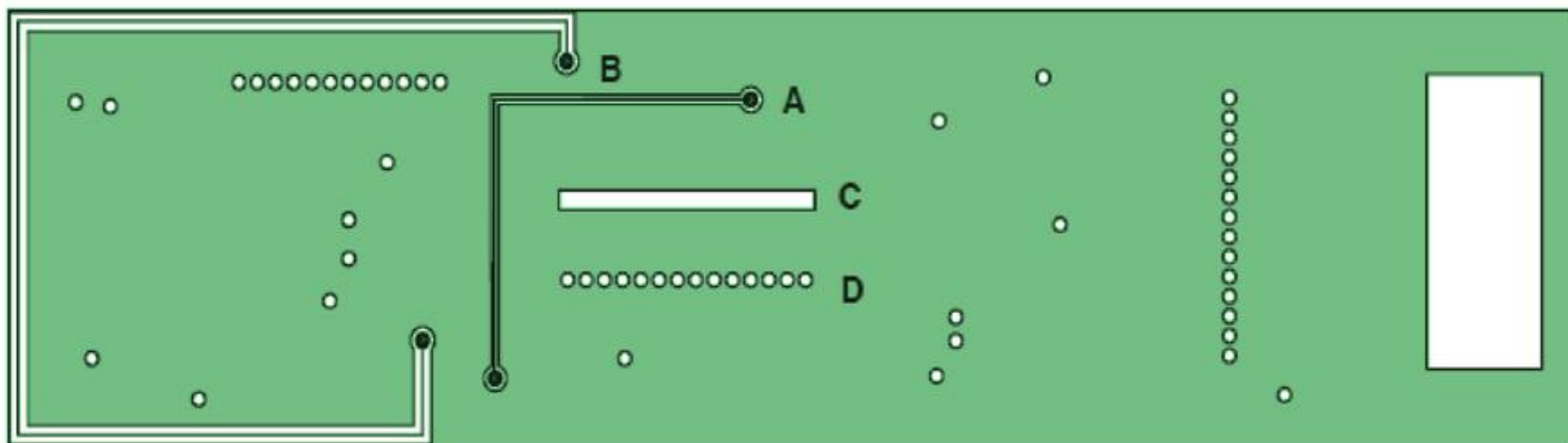
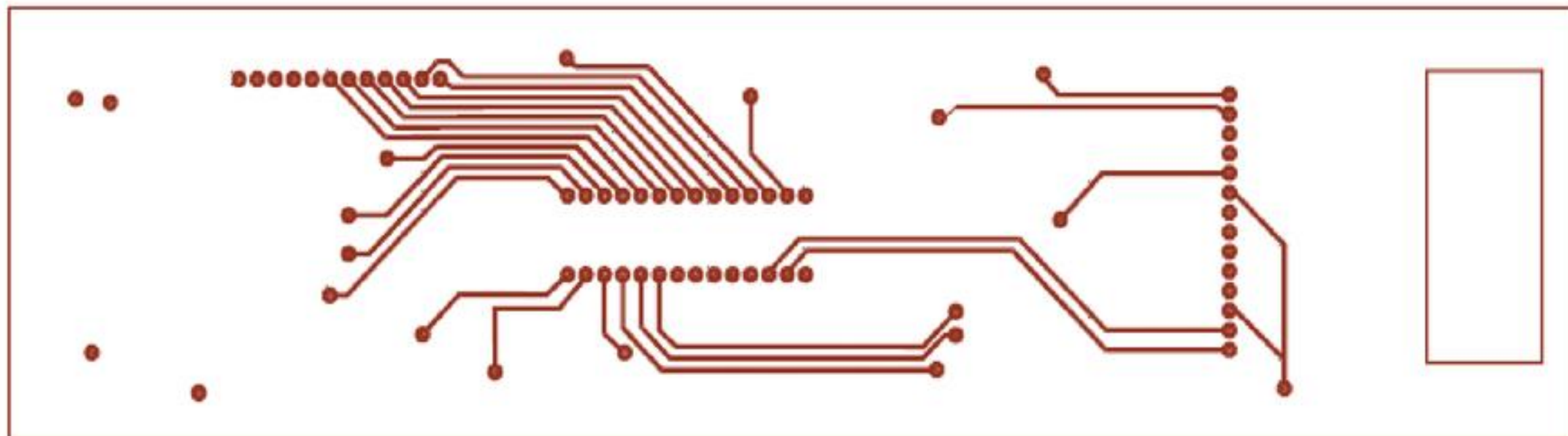
Izbira optimalne strukture plasti PCB



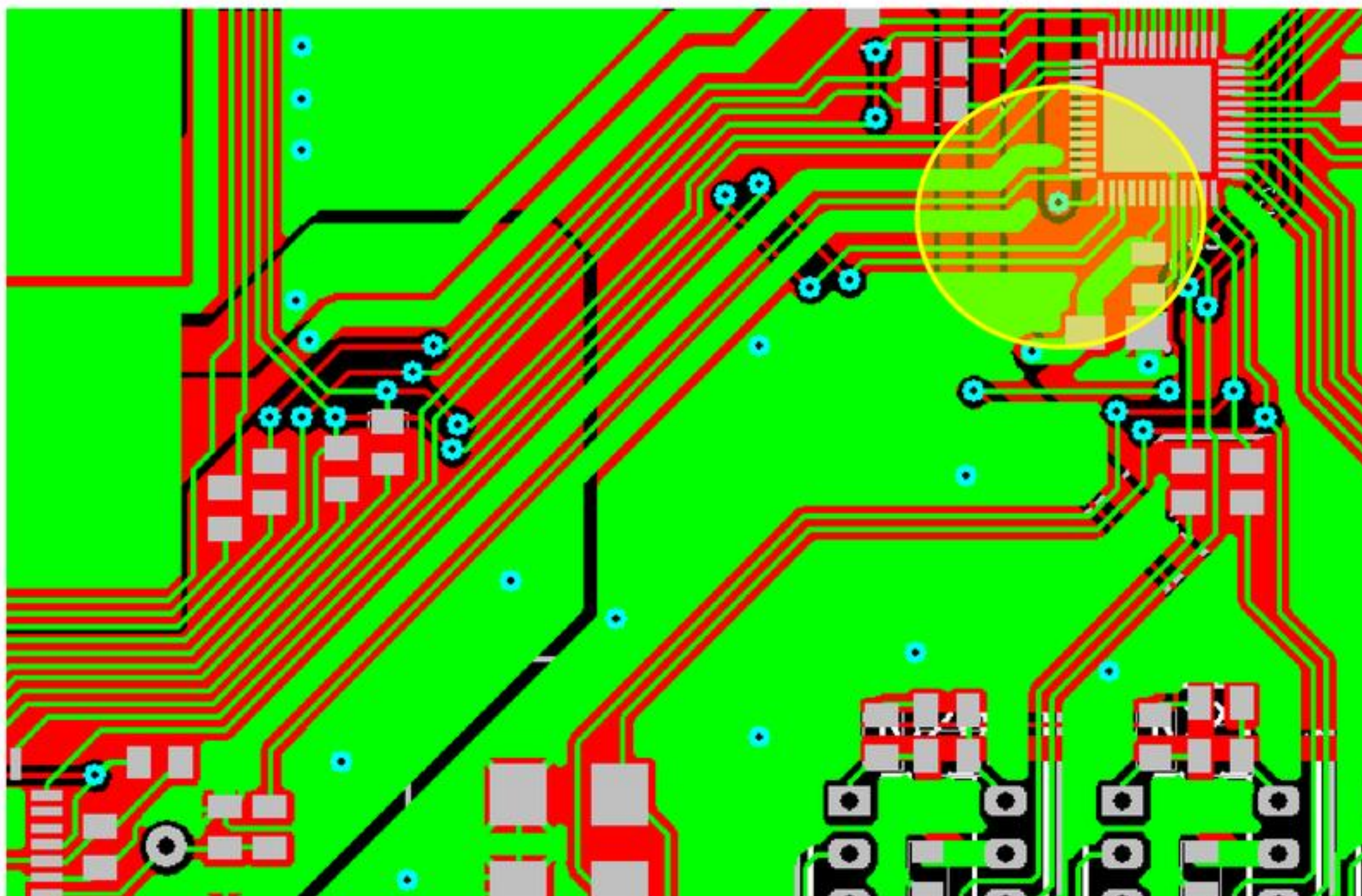
Ukrepi na dvoplastnih vezjih



Prekinitev zrcalne ravnine



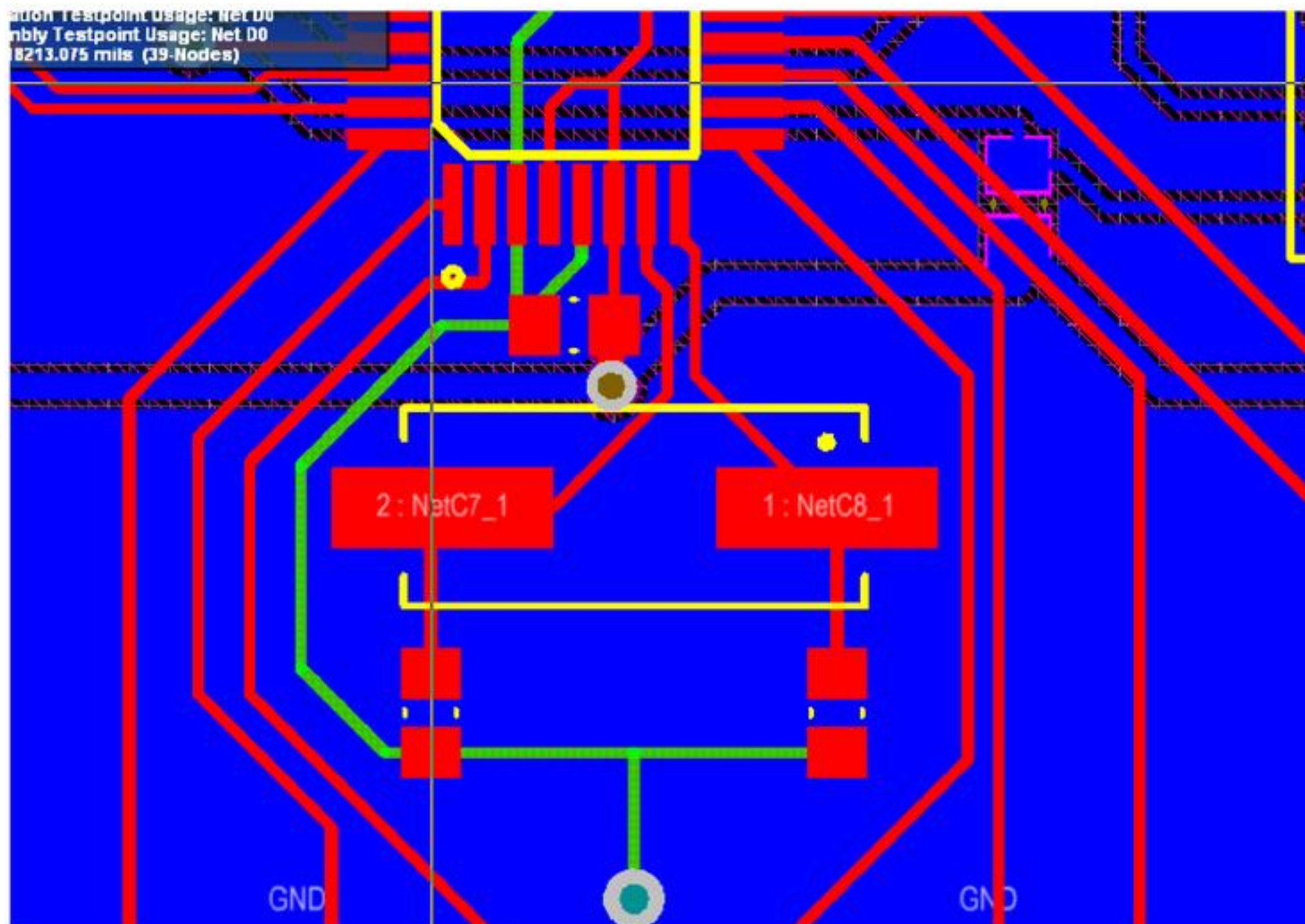
Prekinitev zrcalne ravnine



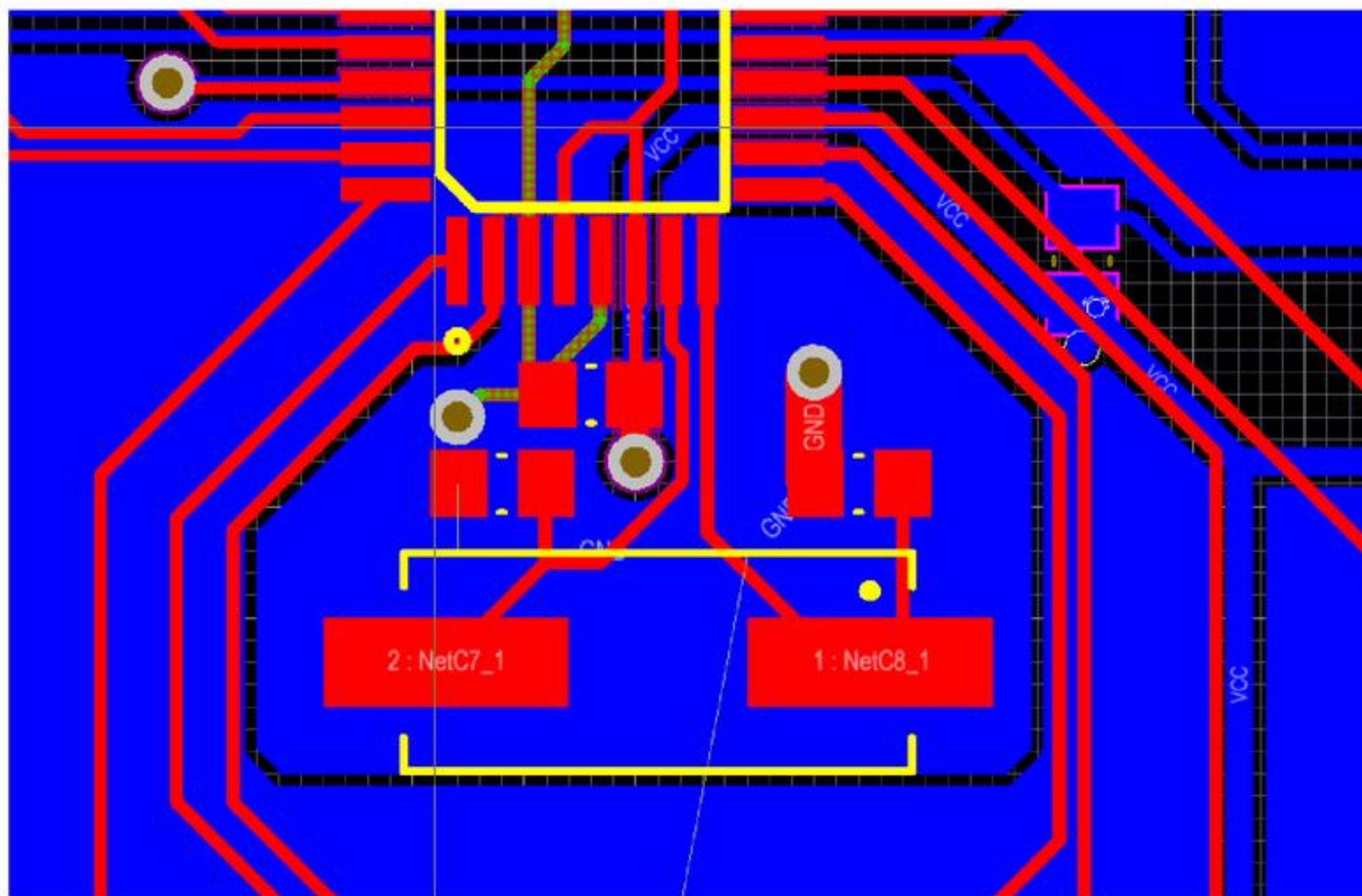
Segmentacija zrcalne ravnine



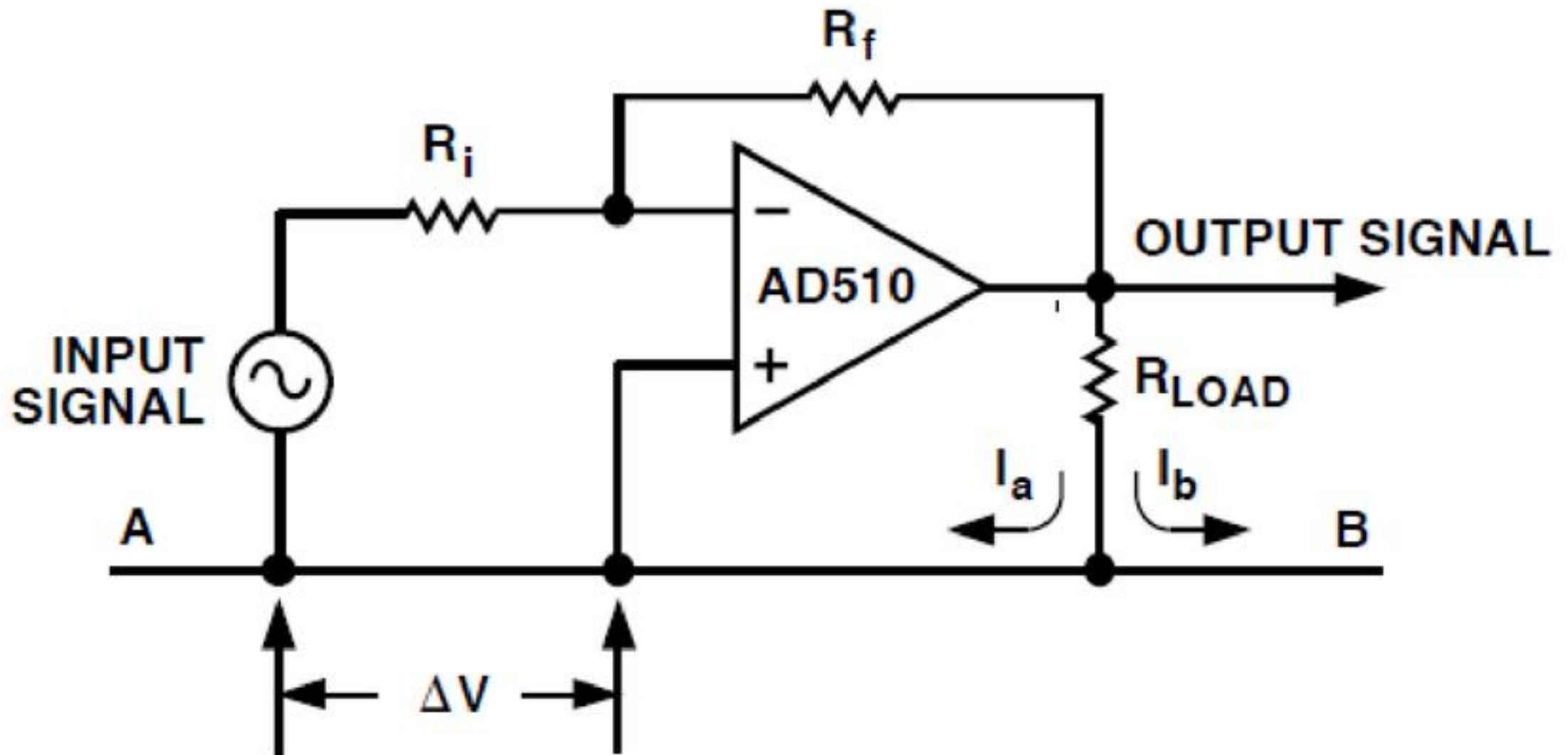
Primer napačnega priklopa kristala



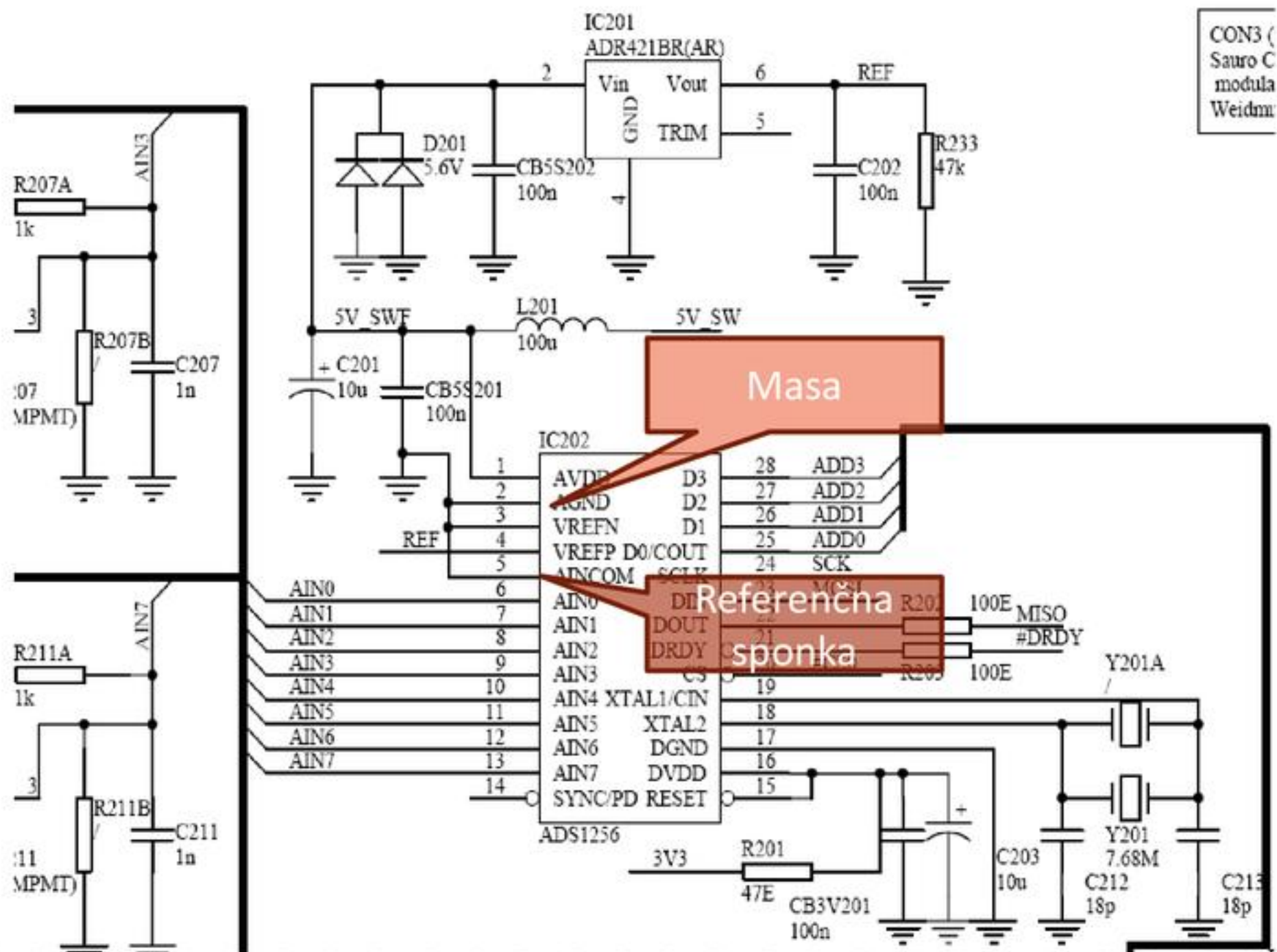
Popravek



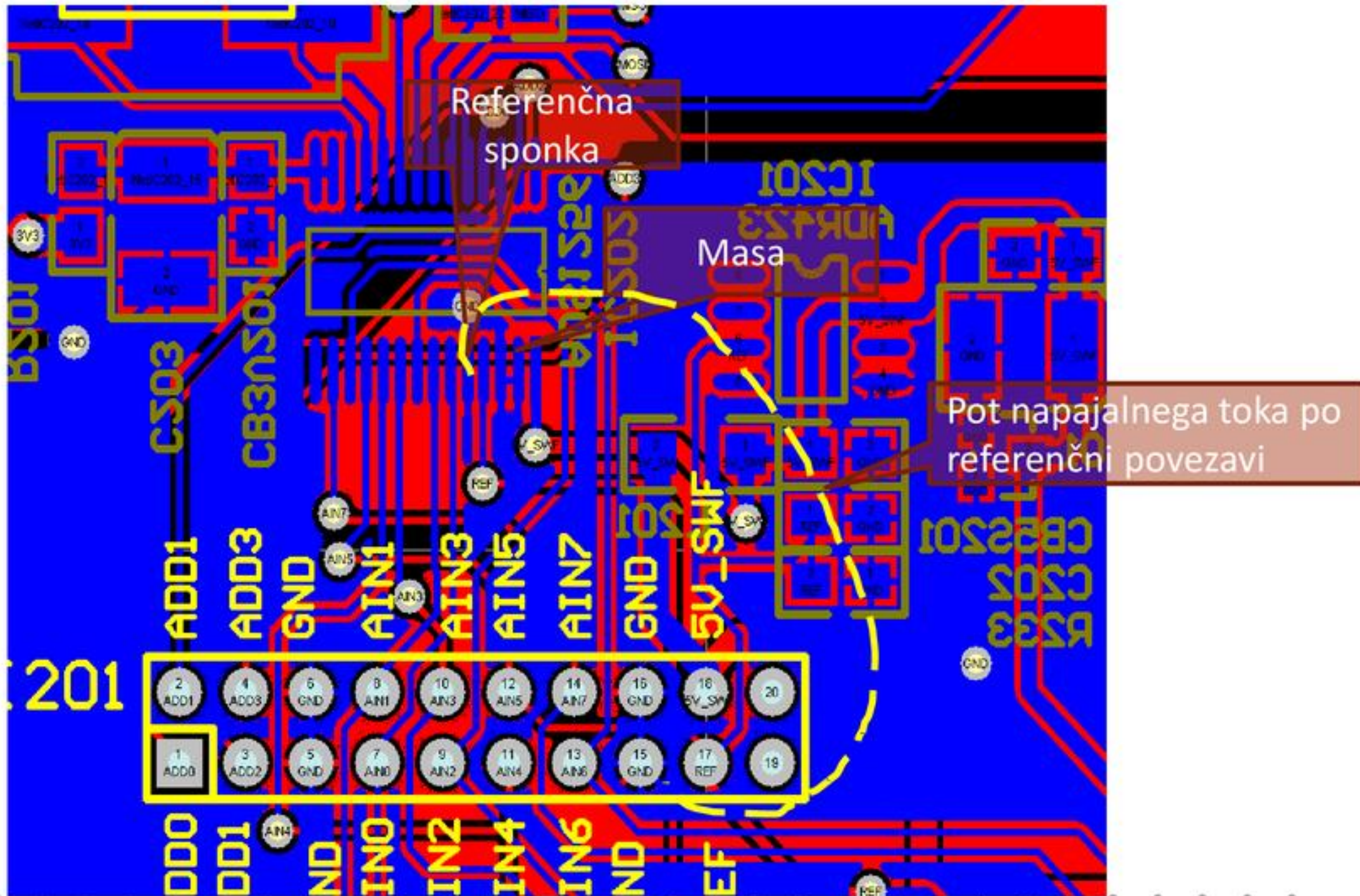
Problem skupne mase



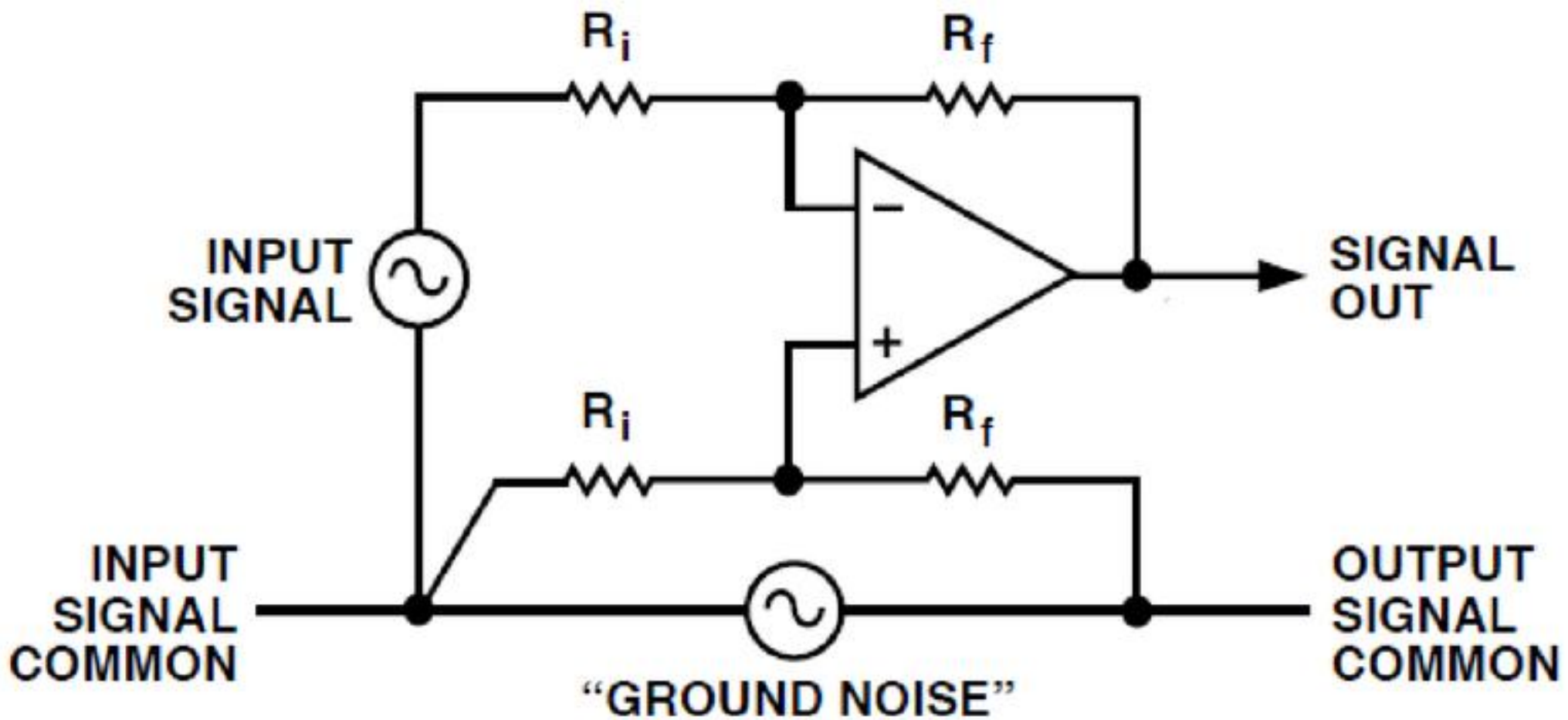
Problem konduktivnih motenj preko mase



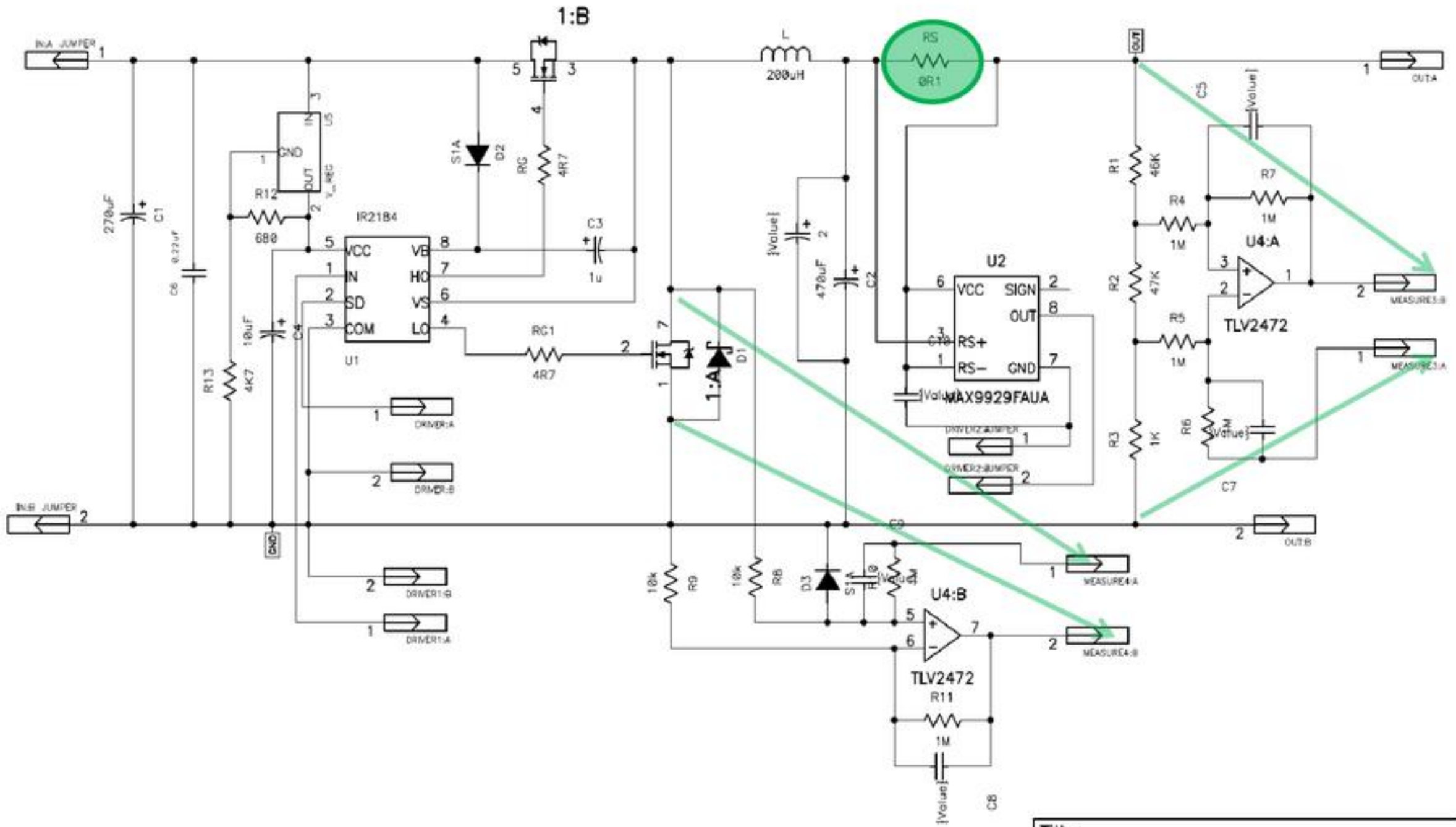
Problem konduktivnih motenj preko mase



Diferencialni ojačevalnik

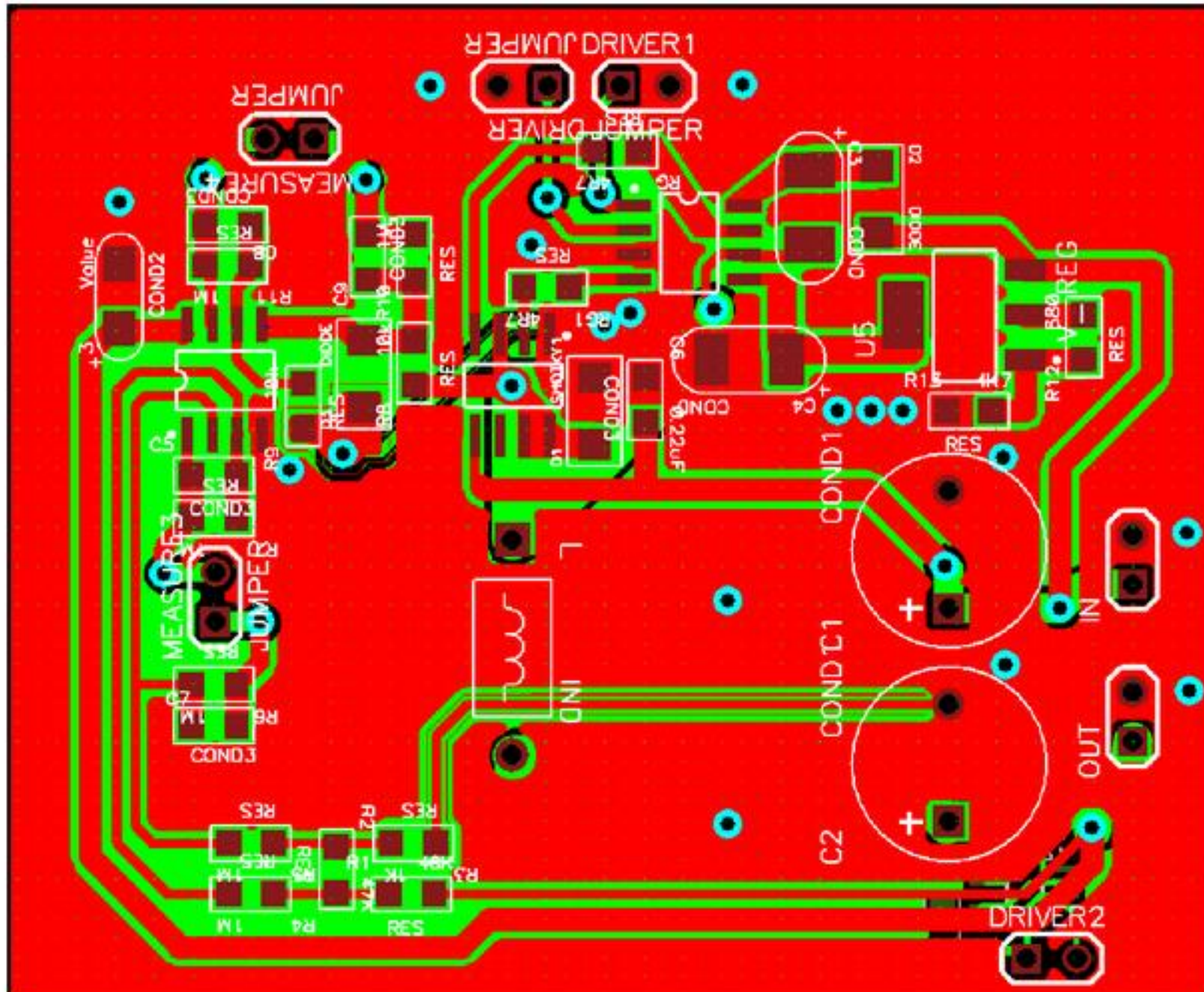


Diferencialni zajem signala

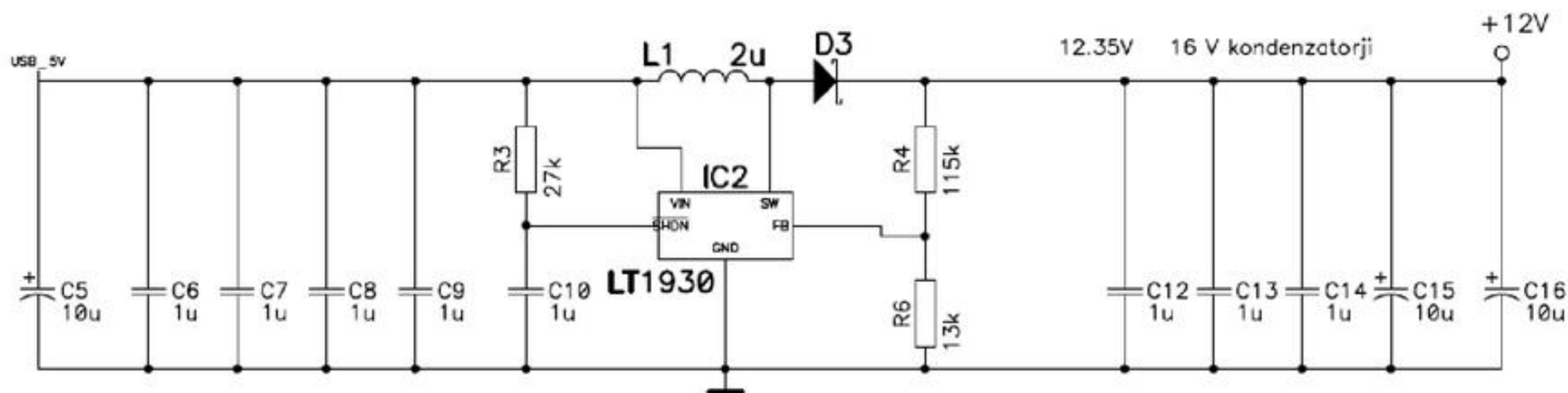


Title

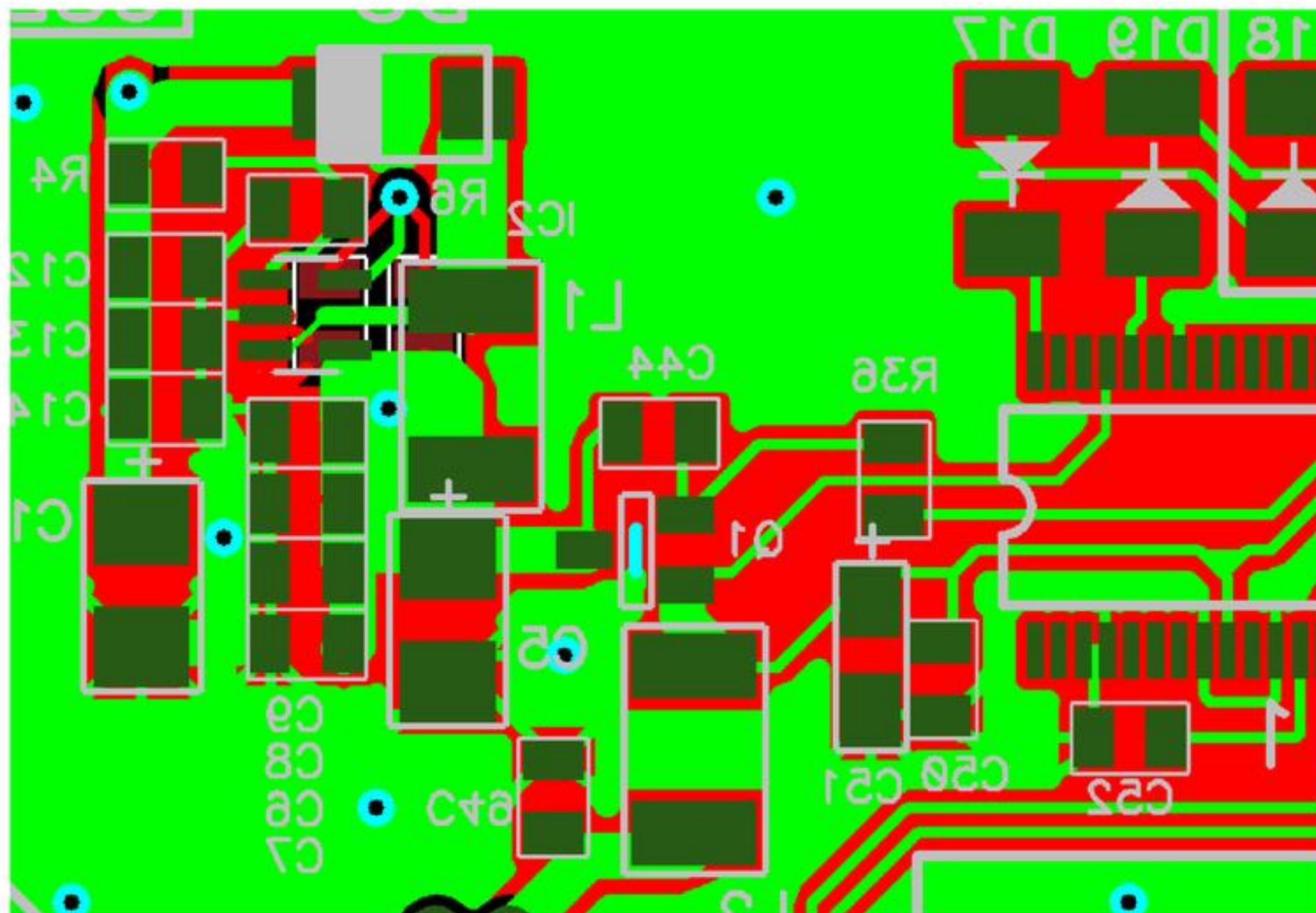
Diferencialni zajem signala



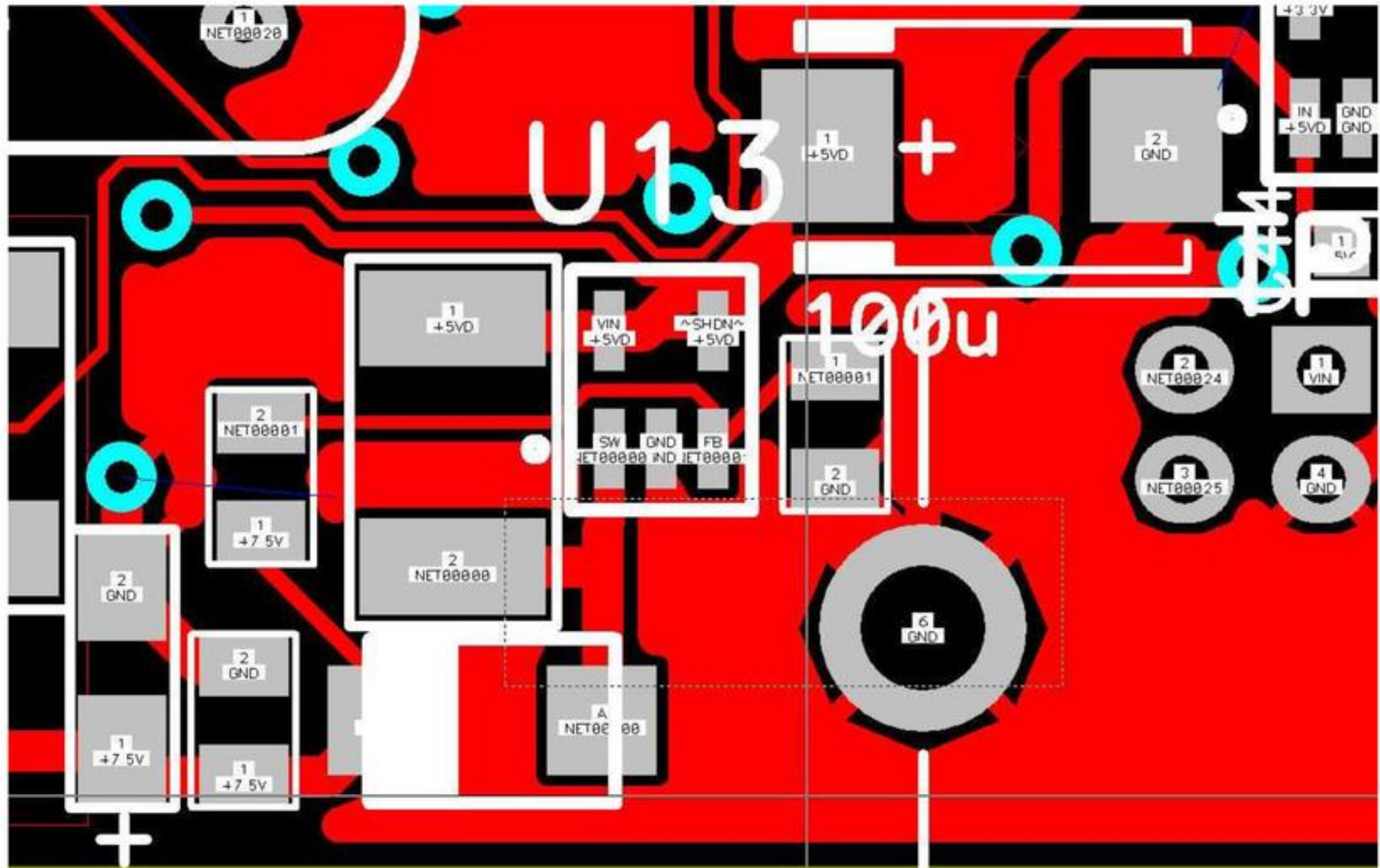
Stikalni DC-DC pretvorniki



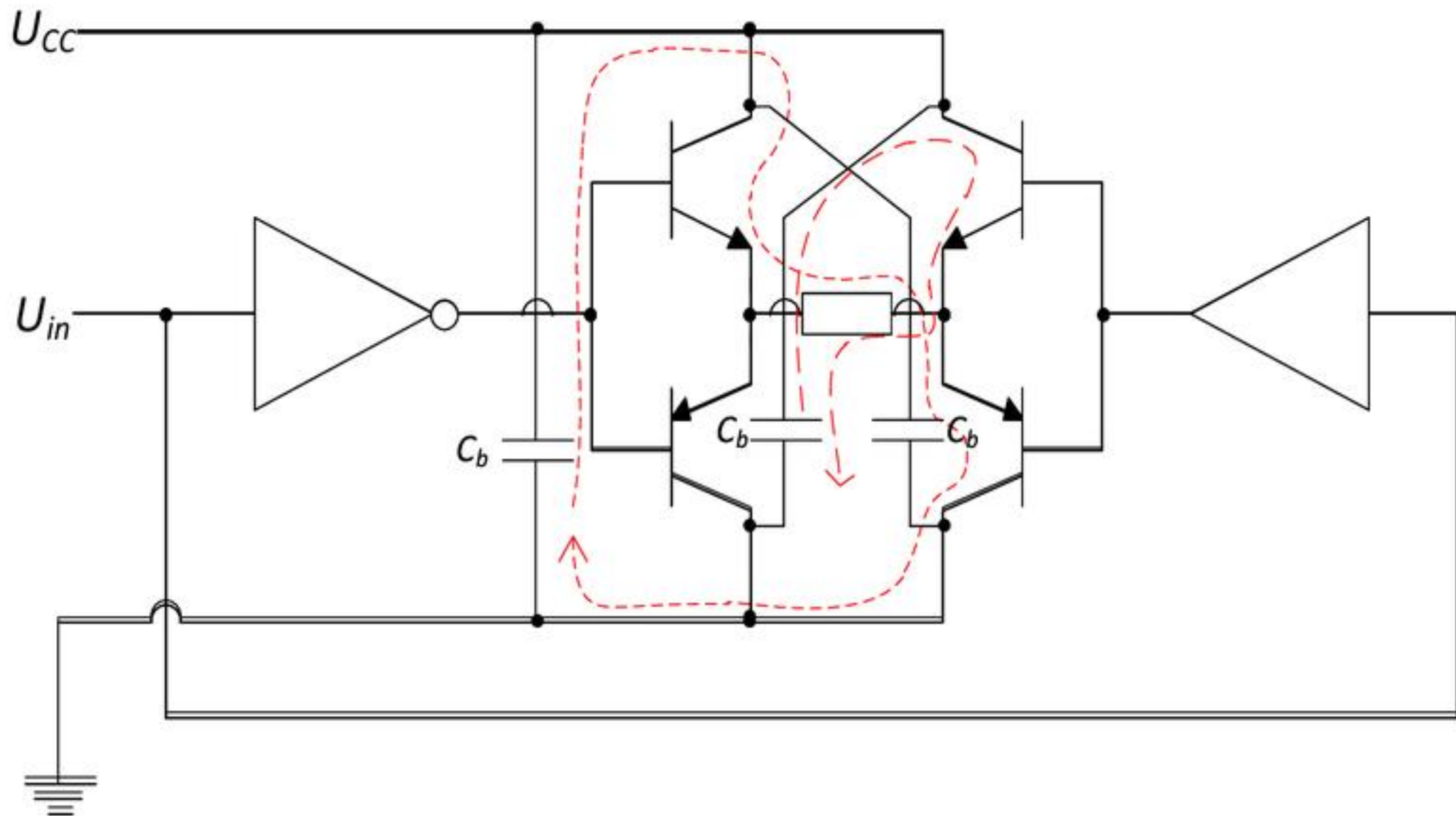
Postavitve kondenzatorjev, tokovne zanke



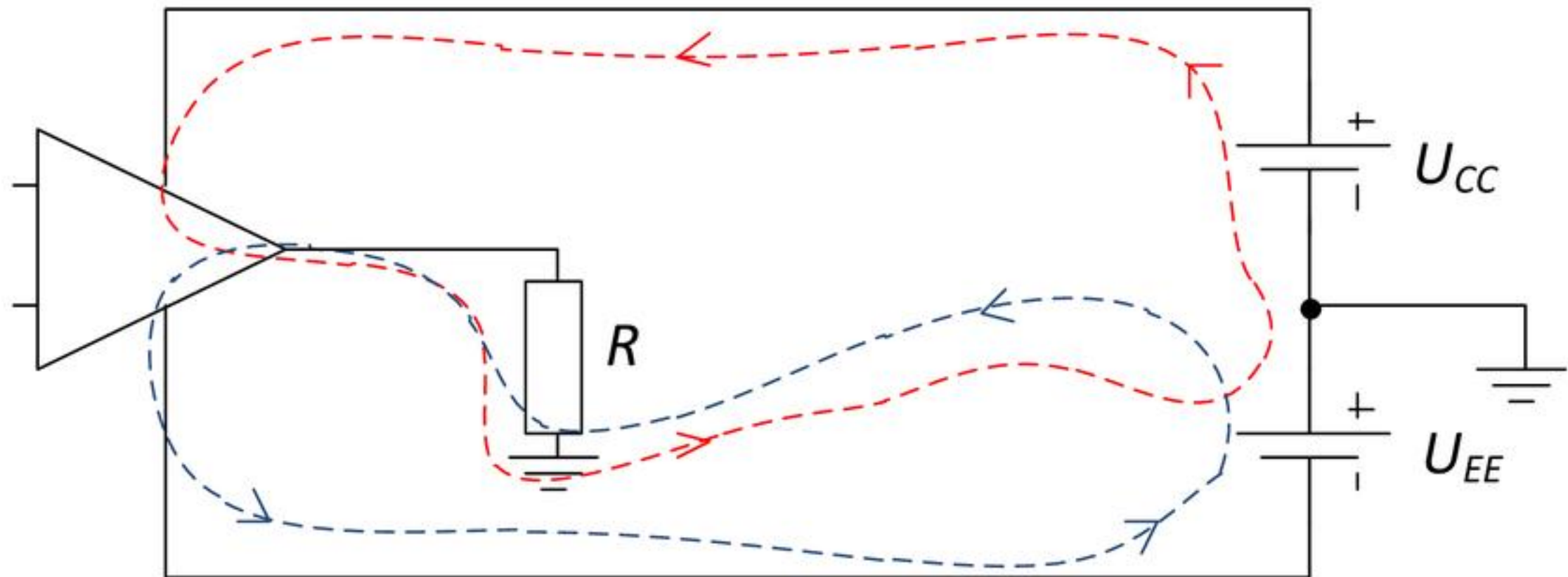
Presluh



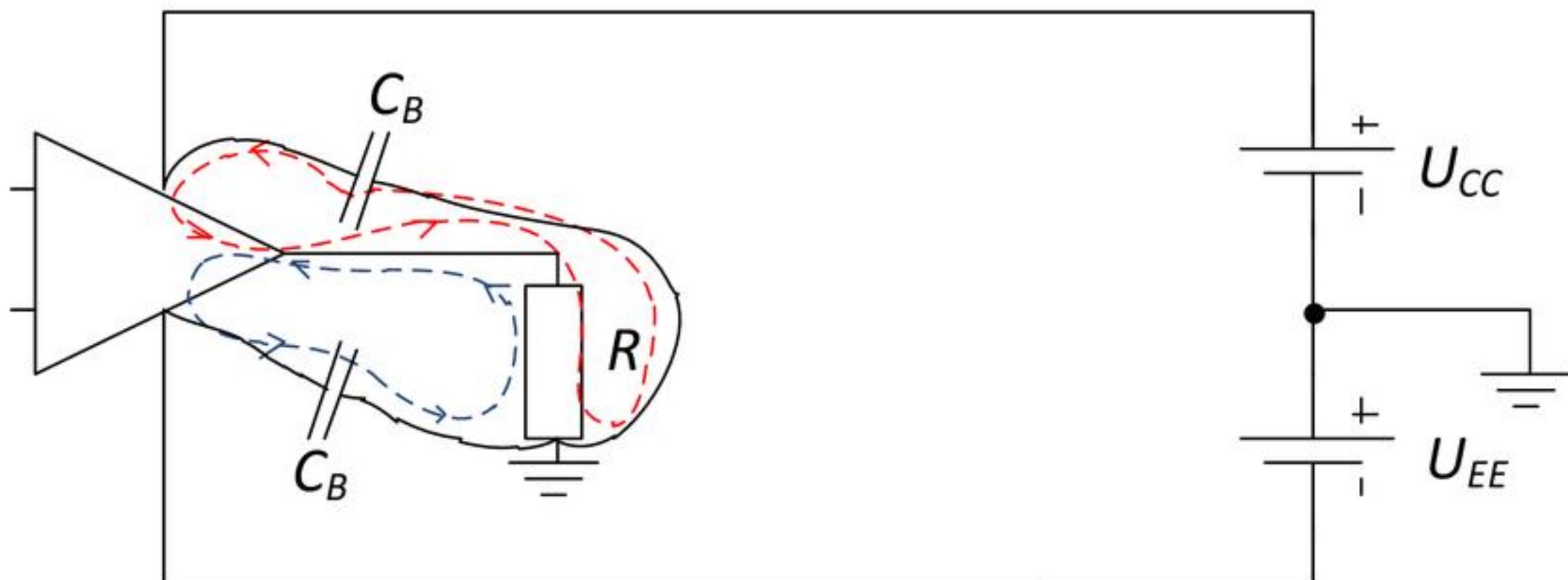
Postavitev blokirnega kondenzatorja



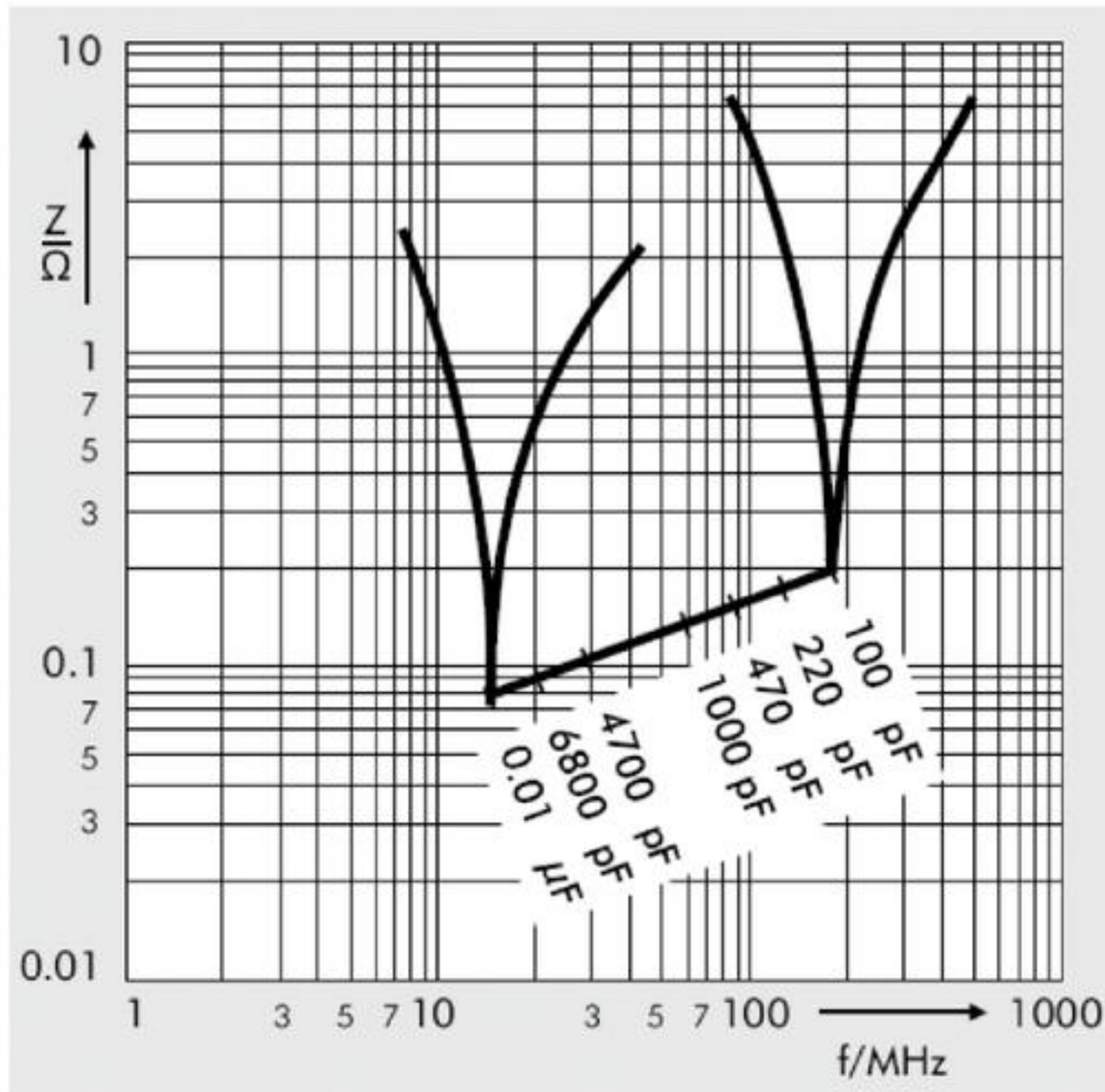
Postavitev blokirnega kondenzatorja



Postavitev blokirnega kondenzatorja

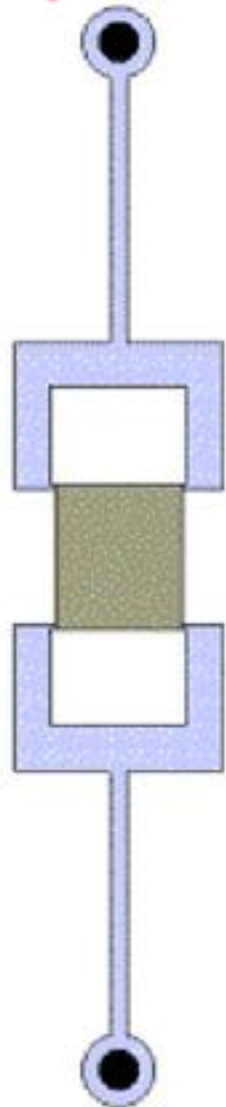


Kondenzator? Tuljava? Oboje!

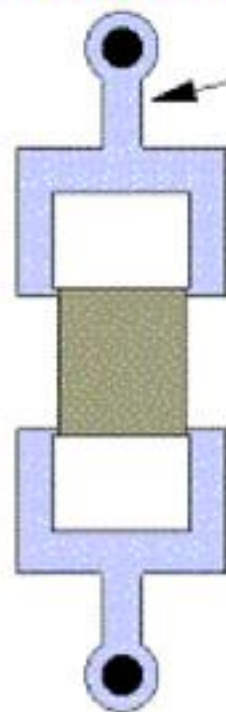


Priključitev blokirnega kondenzatorja

Always
poor

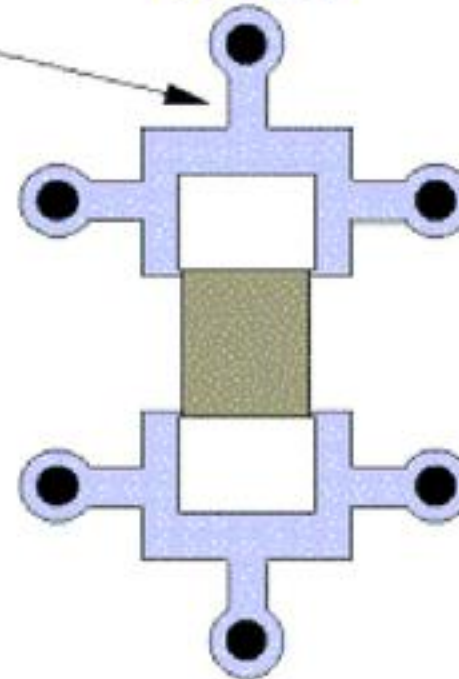


Often
adequate



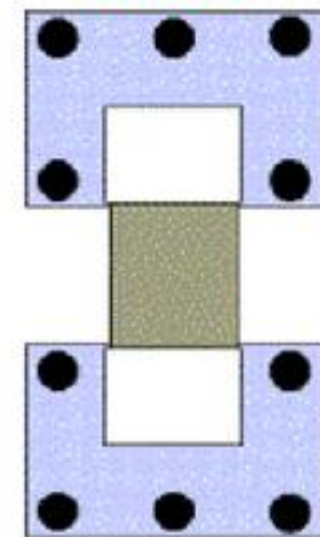
Tracks as
short and
wide as
practicable

Good



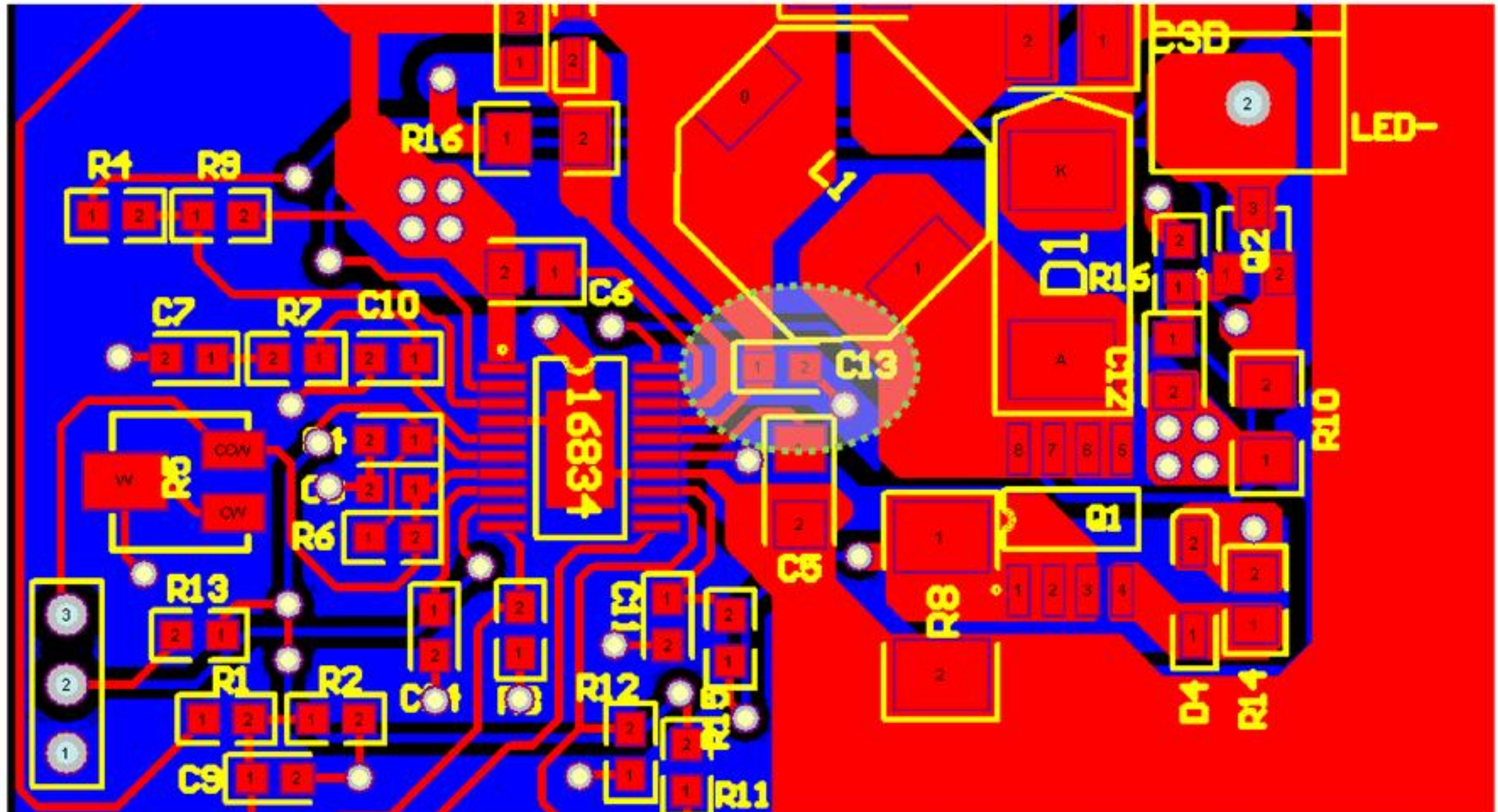
(Solder
masks not
shown)

Best

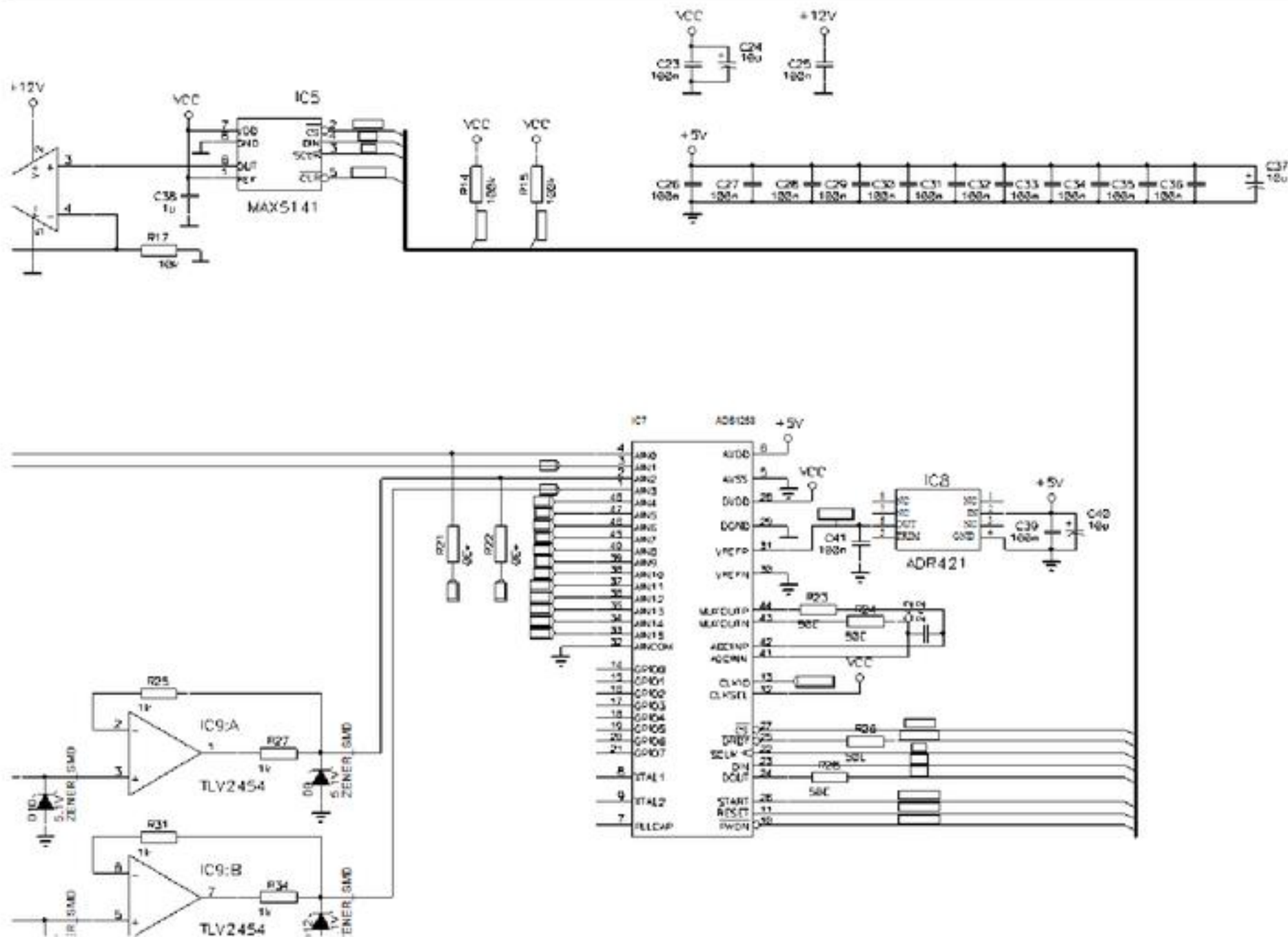


This example shows a decoupling capacitor
The same considerations apply for IC connections to planes

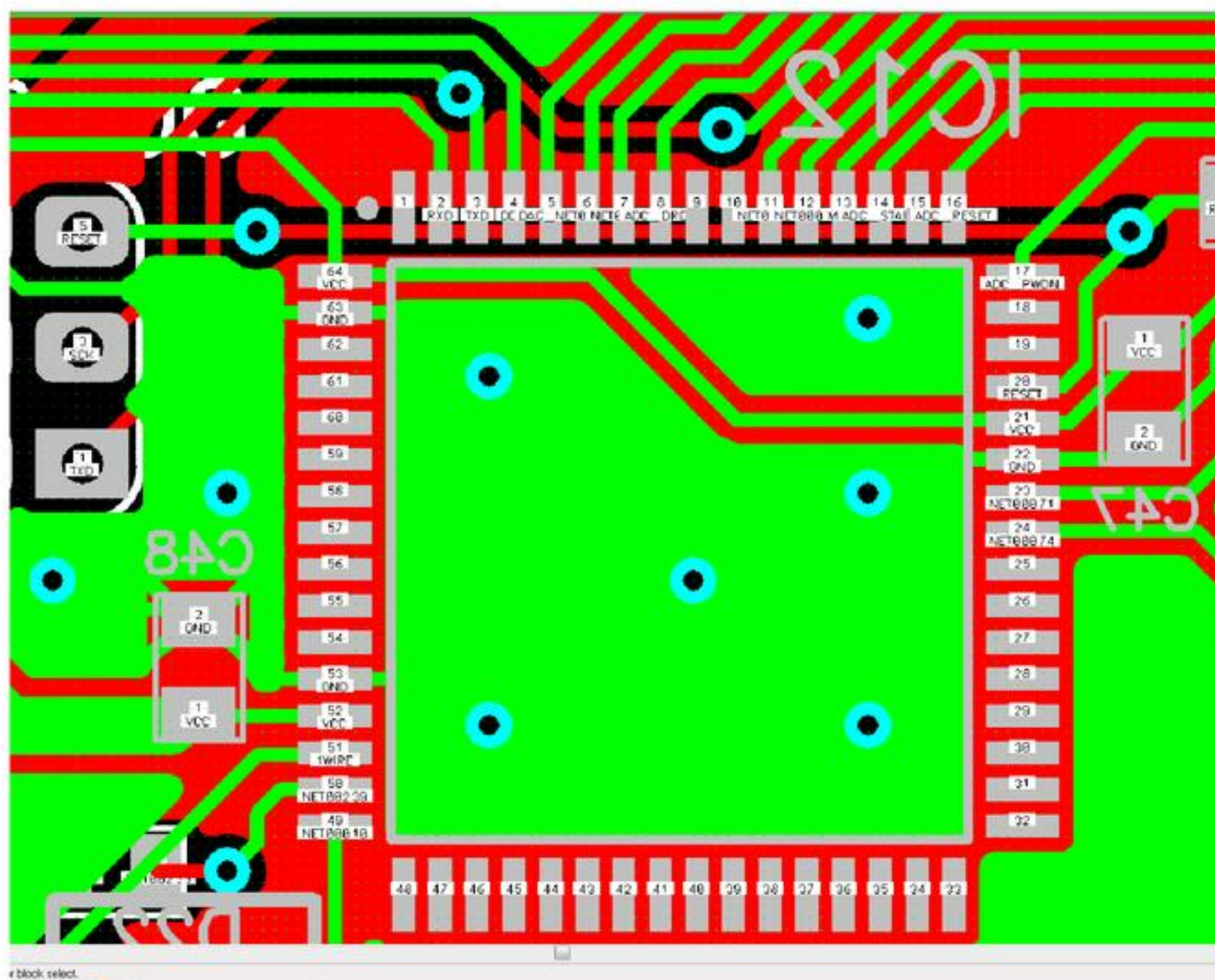
Postavitev blokirnega kondenzatorja



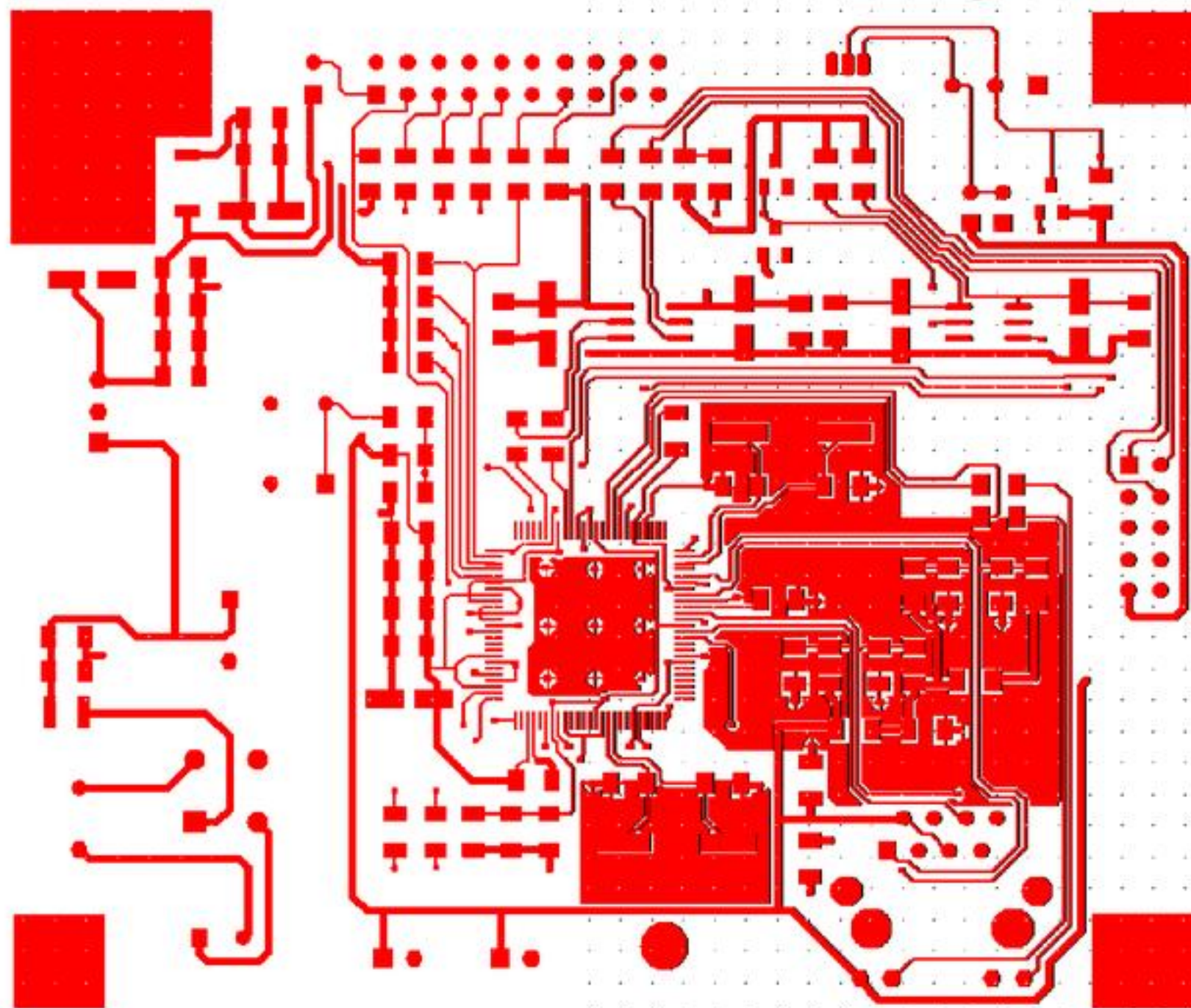
Postavitev blokirnih kondenzatorjev



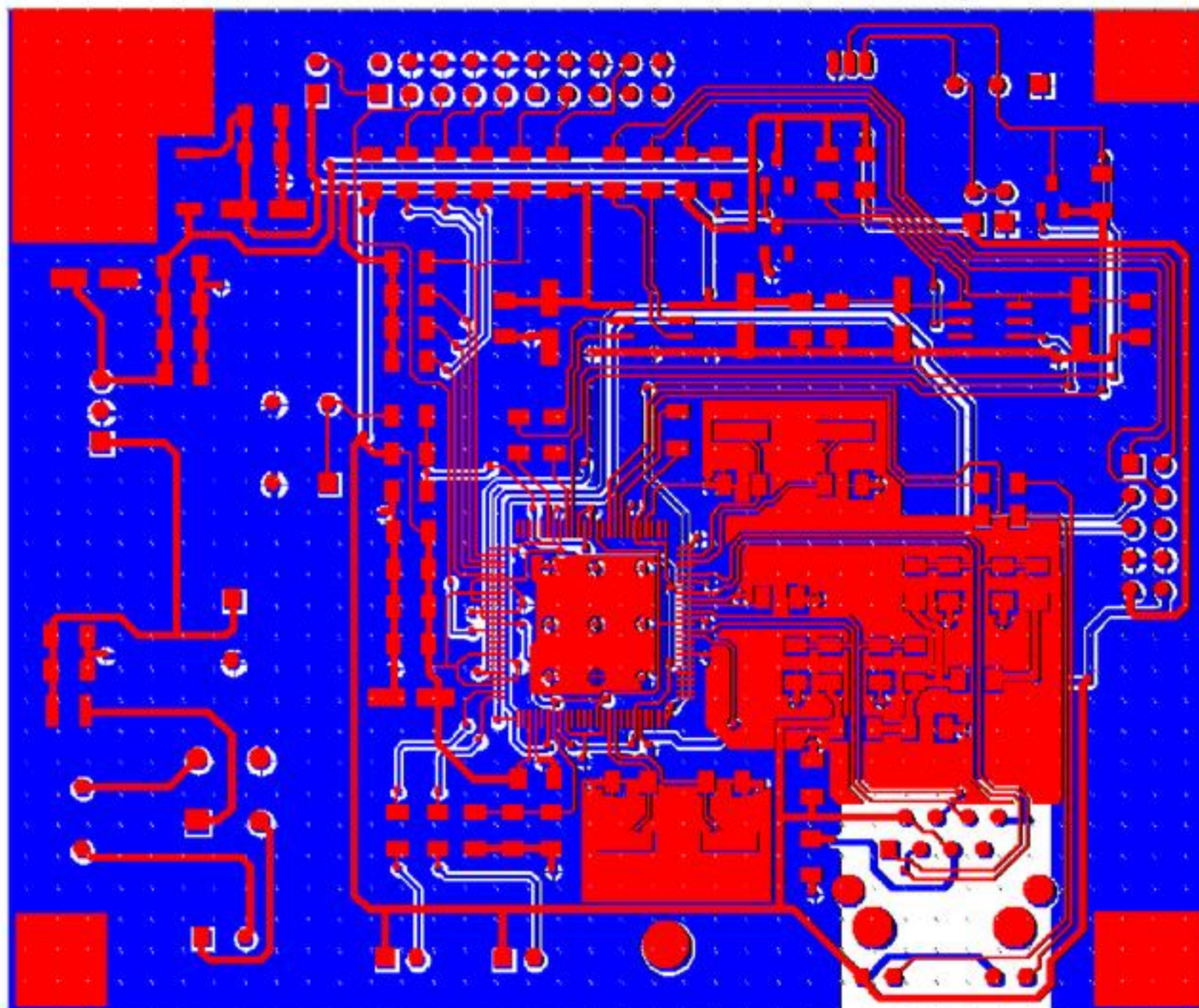
Postavitev blokirnih kondenzatorjev



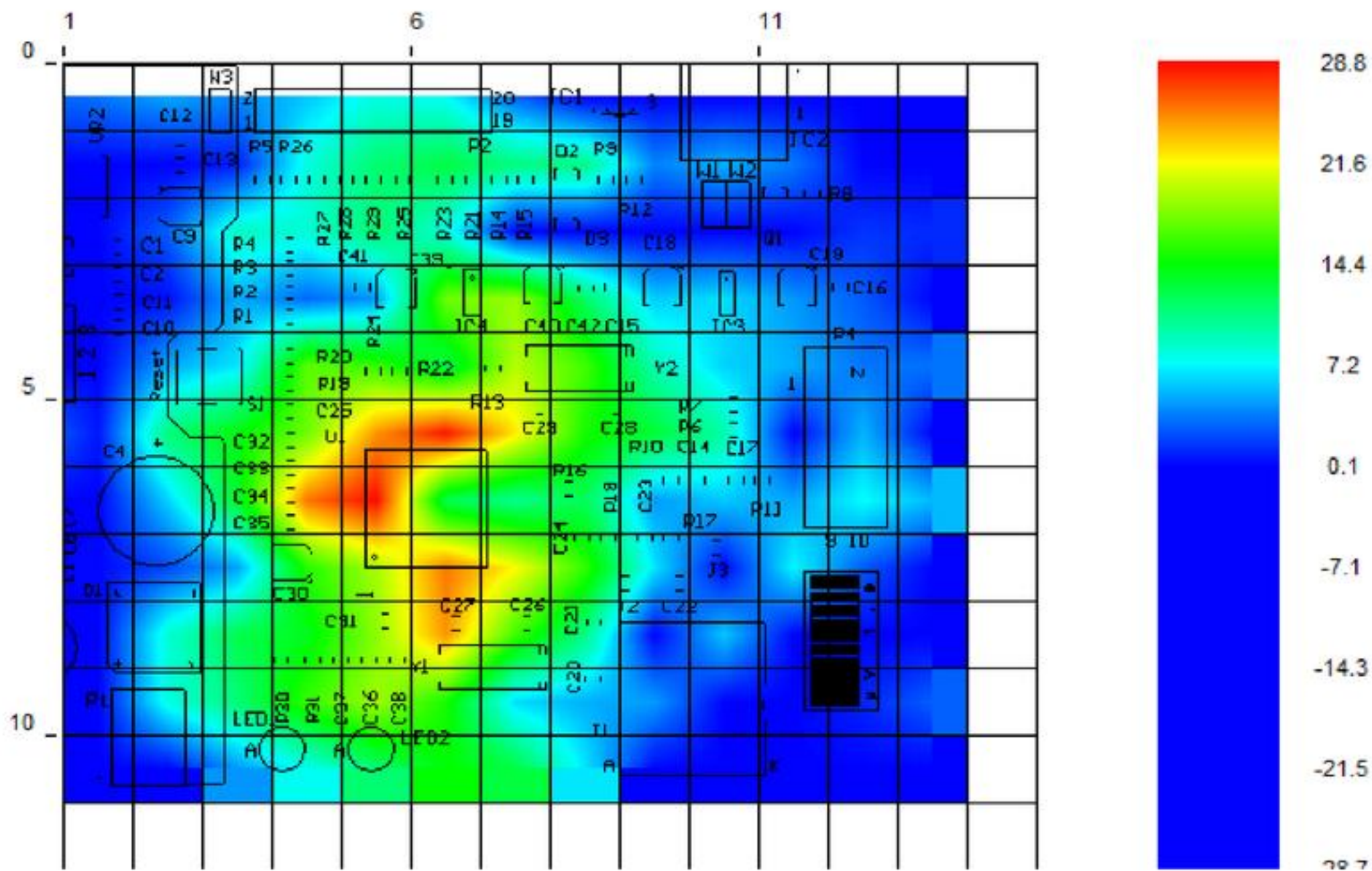
Postavitve blokirnih kondenzatorjev



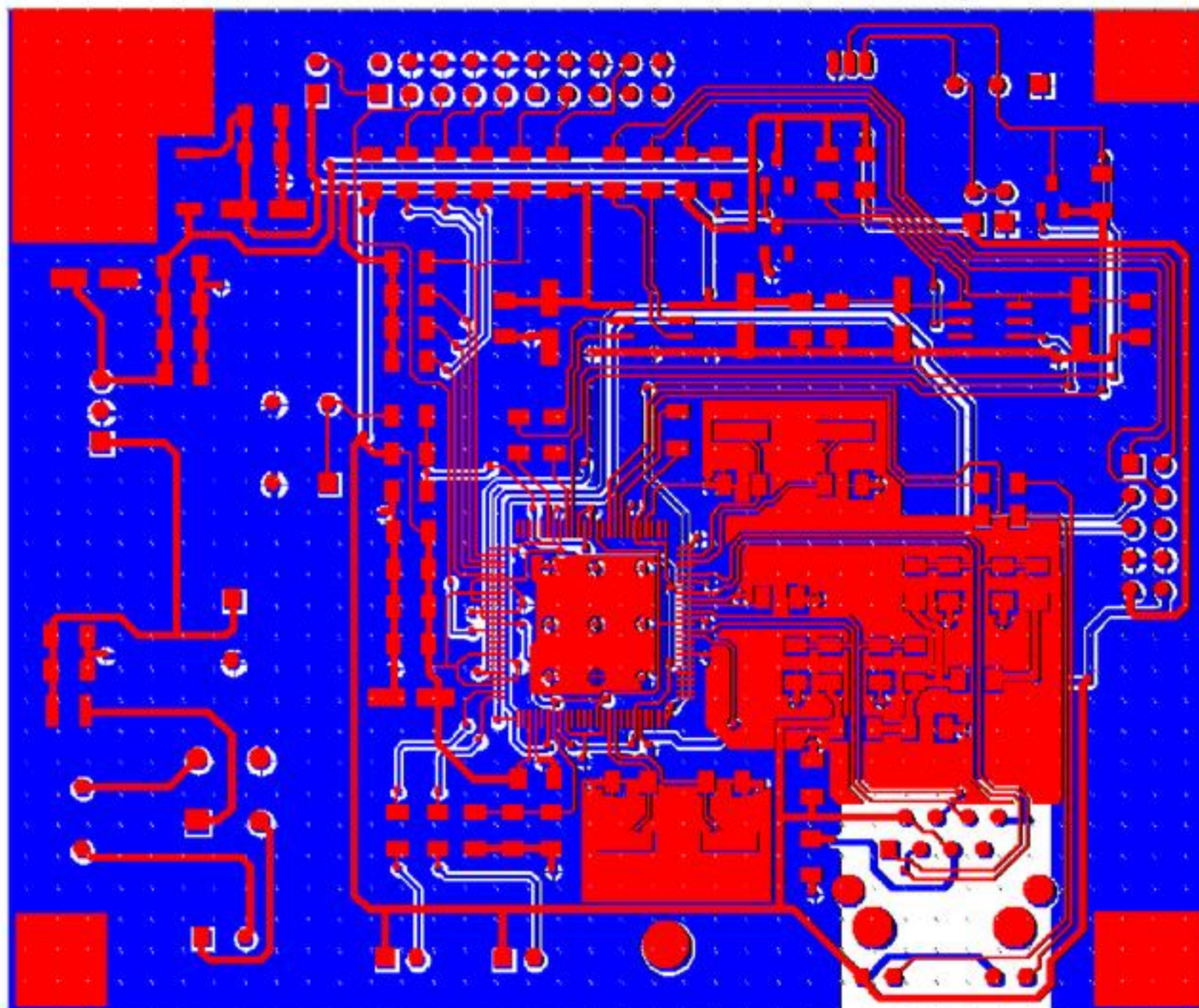
Postavitev blokirnih kondenzatorjev



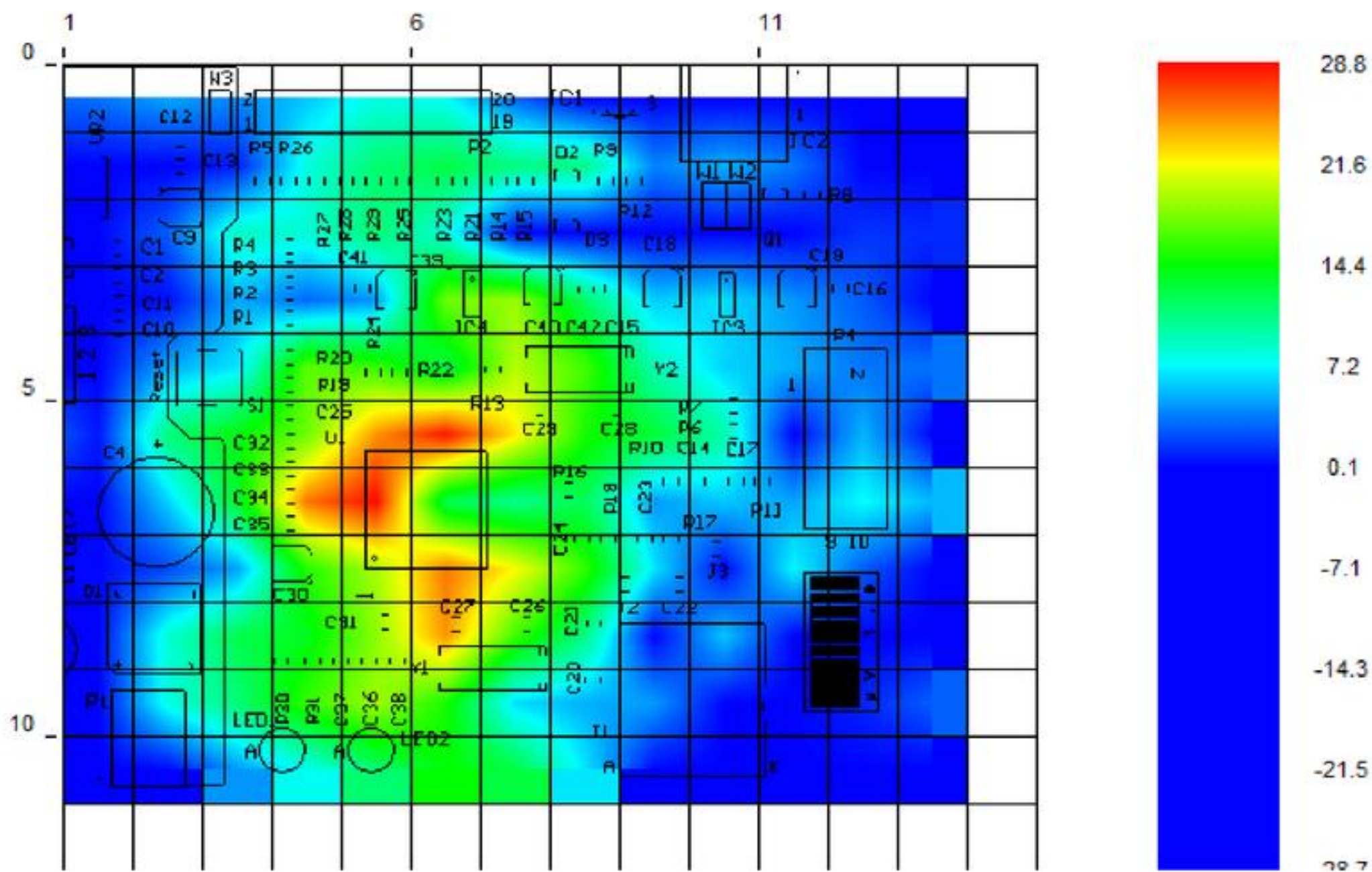
Jakost E polja pri 50 MHz



Postavitev blokirnih kondenzatorjev



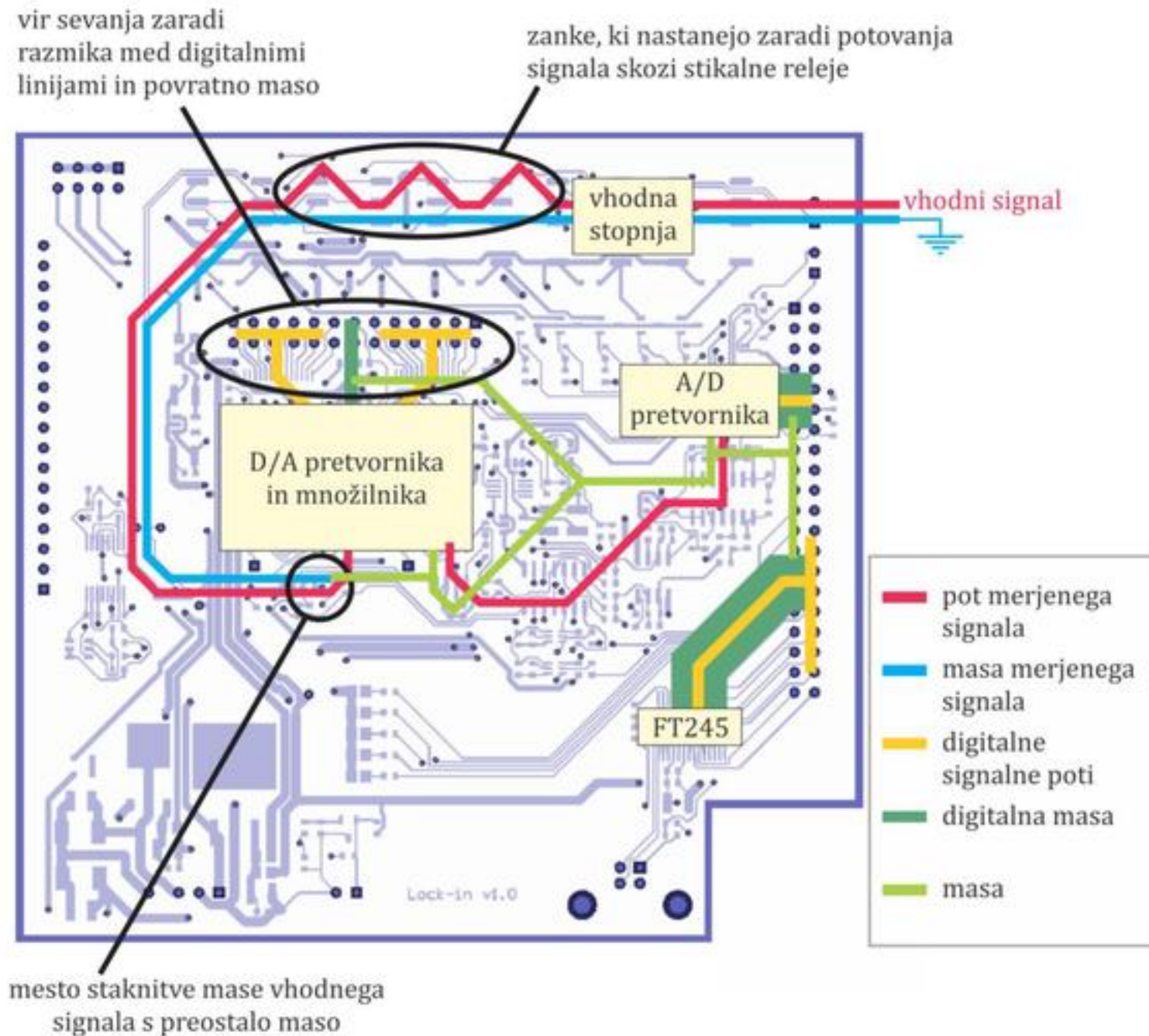
Jakost E polja pri 50 MHz



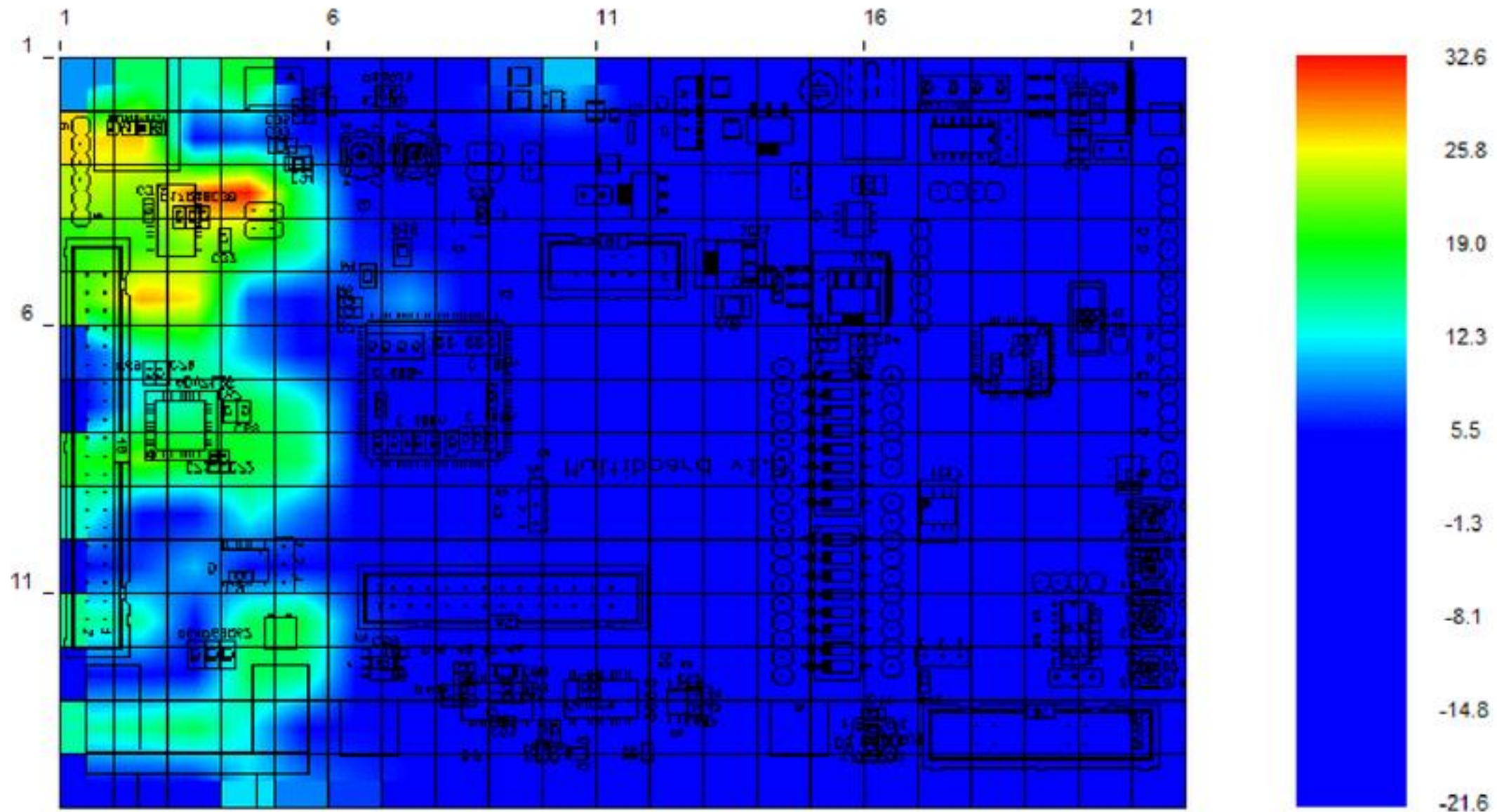
EM scan



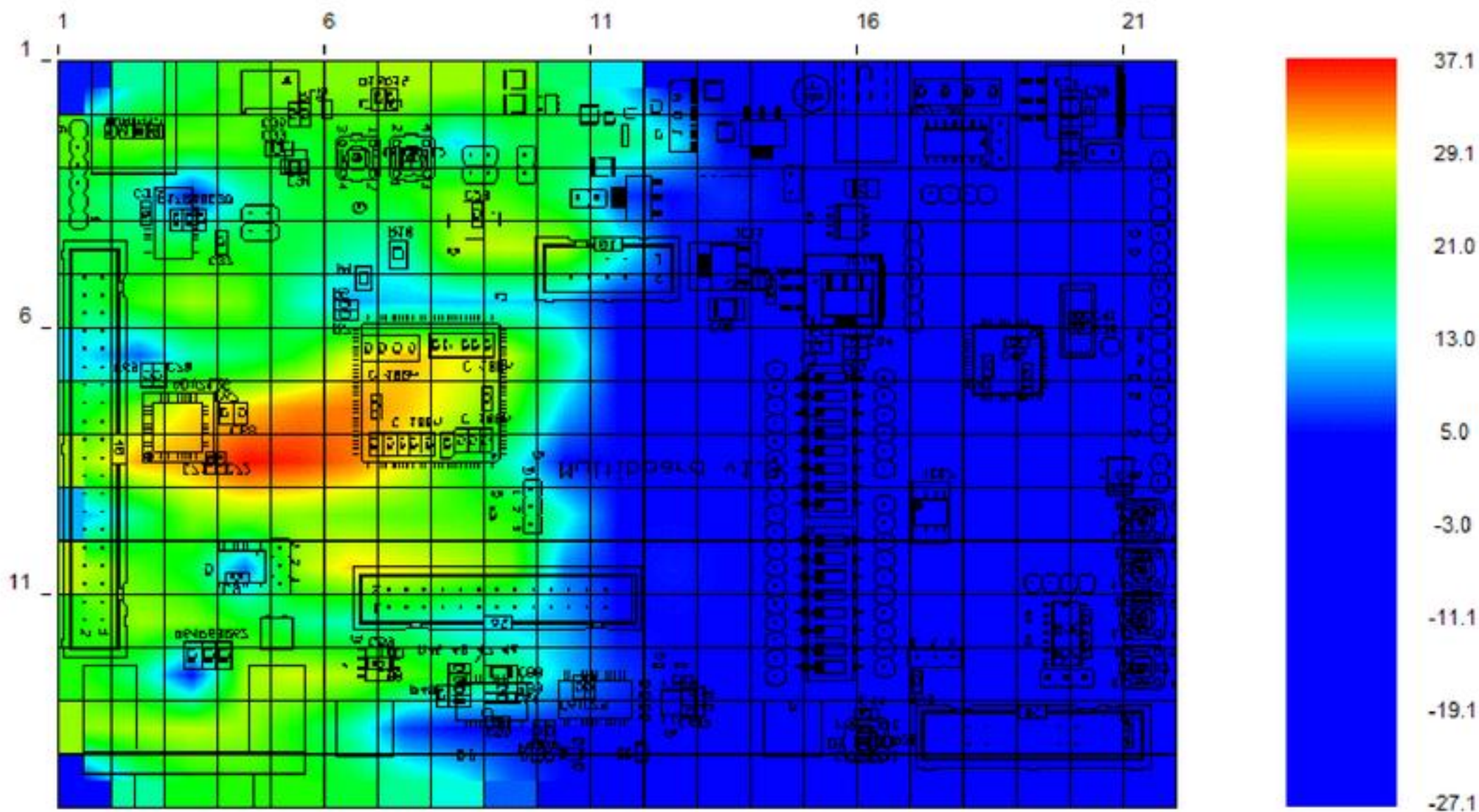
Viri sevanj v digitalno-analognem vezju



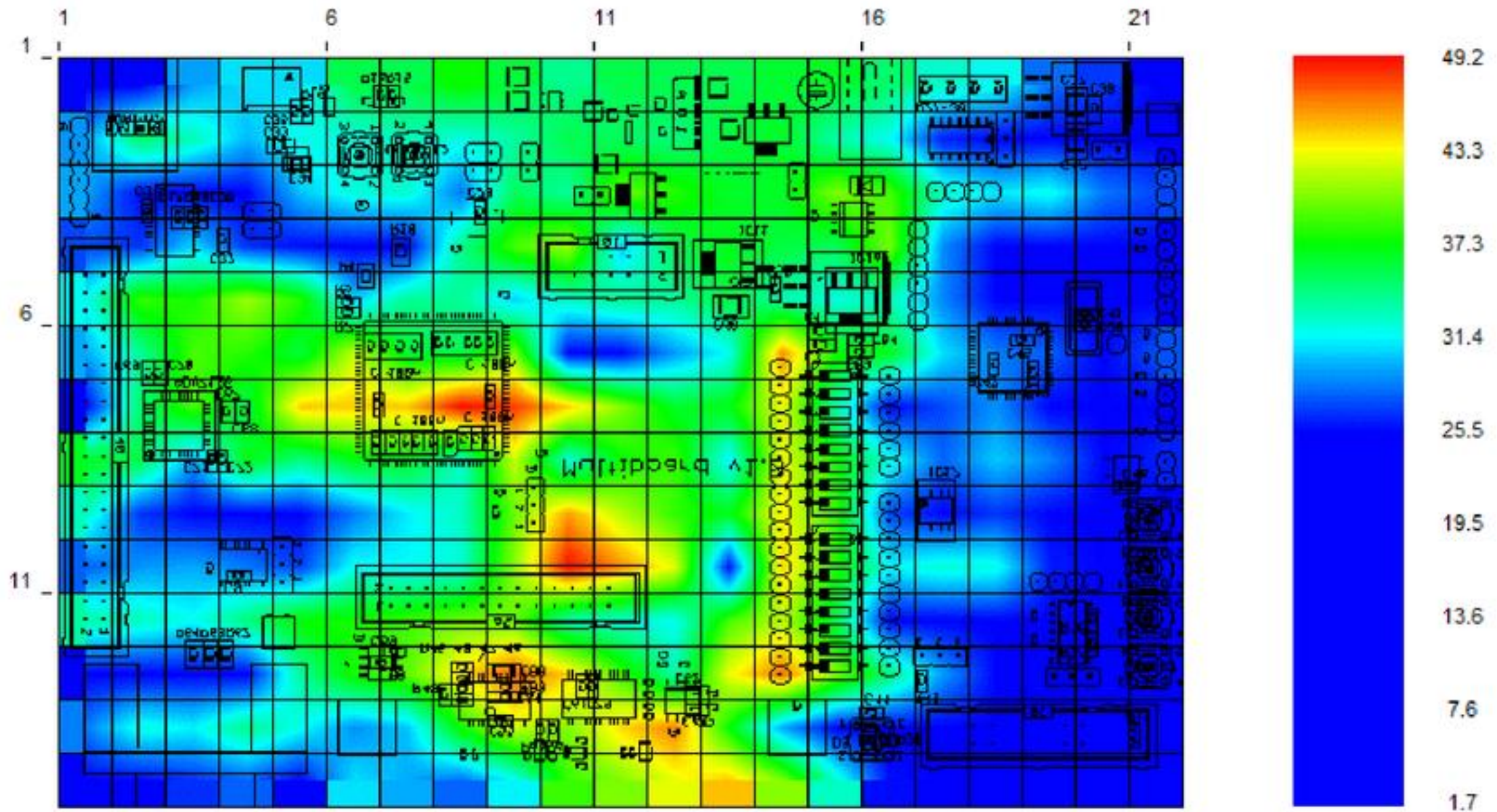
Jakost E polja pri 24 MHz



Jakost E polja pri 32 MHz



Jakost E polja pri 100 MHz



Prijetno branje

- Mark I. Montrose, *Printed Circuit Board Design Techniques for EMC Compliance*, Wiley-Interscience IEEE, ISBN 0-7803-5376-5, New York, 2000.
- Howard W. Johnson, *High-speed digital design*, Prentice-Hall Inc., Upper SaddleRiver, NJ, ISBN 0-13-395724-1, 1993.
- A. E. Ward, J. A. S. Angus, *Electronic Product Design*, Chapman & Hall, ISBN 0-412-63200-4, London, 1996.
- C.A. Harper, *Electronic Packaging and Interconnection Handbook*, 3rd edition, The McGraw-Hill Companies, Inc.
- Rao R. Tummala, Ed., "Fundamentals of Microsystem Packaging", McGraw Hill, New York, 2001.
- Henry W. Ott, *Electromagnetic Compatibility Engineering*, J. Wiley & Sons, ISBN 978-0-470-18930-6, 2009.
- <http://lpvo.fe.uni-lj.si/izobrazevanje/2-stopnja-un/konstruiranje-elektronskih-naprav-ken/>